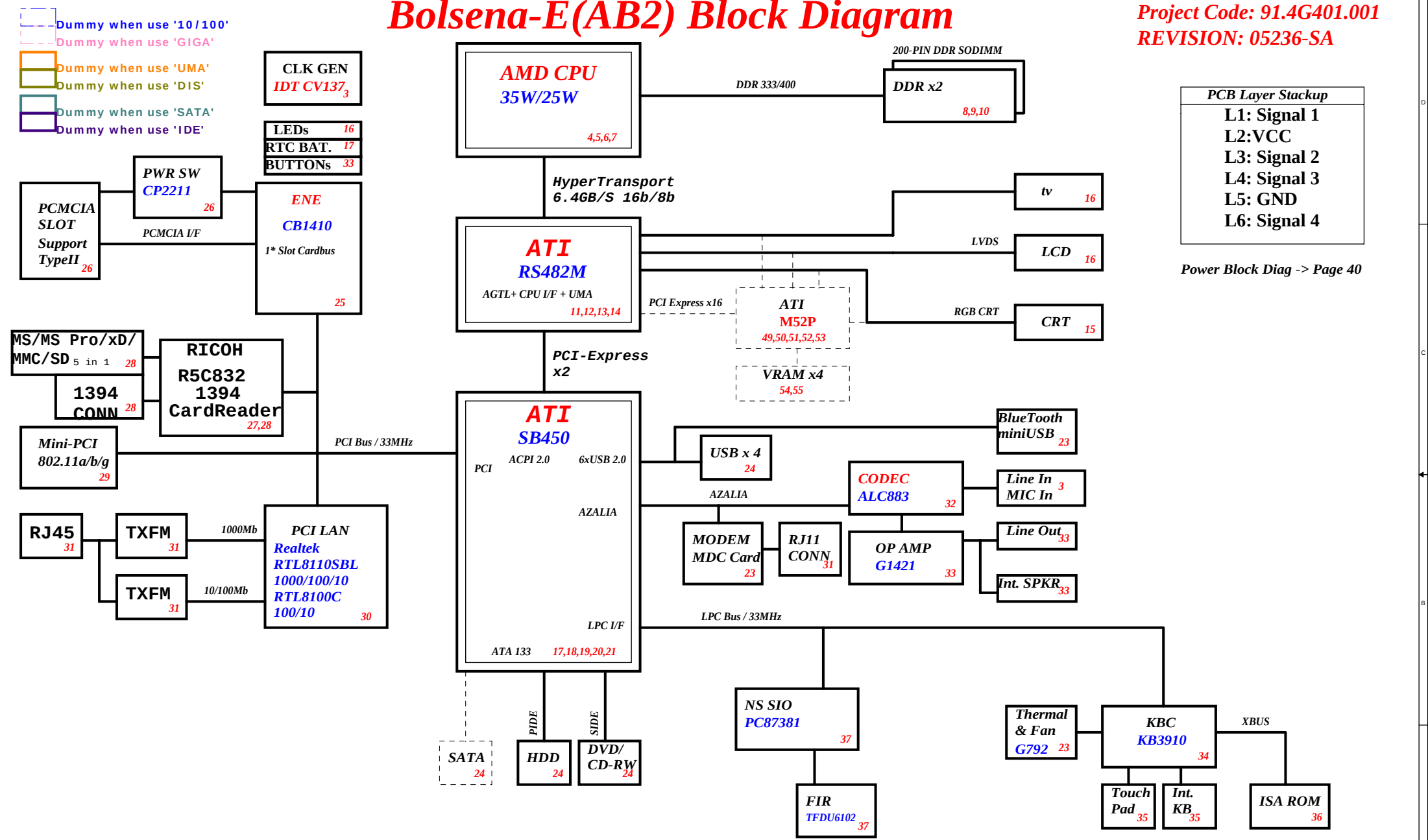


See 'TEXT' in 0MEMO or 1MEMO property in component

Bolsena-E(AB2) Block Diagram

Project Code: 91.4G401.001
REVISION: 05236-SA



PCB Layer Stackup

L1:	Signal 1
L2:	VCC
L3:	Signal 2
L4:	Signal 3
L5:	GND
L6:	Signal 4

Power Block Diag -> Page 40

PCI Routing

	IDSEL	IRQ	REQ/GNT
MiniPCI	21	F	0
LAN	23	H	2
7411	22	E (CardBus)	1
7411	17	G (1394)	3
7411	17	E (FlashMedia)	3

Ref.	function	schematic	BOM

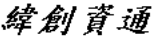
U81	cpu socket	62.10055.121	(DON'T CHANGE) (3mm high)
U80	north bridge	71.RS482.M03	71.RS482.M03 (ver A12)
U43	south bridge	71.SB400.B0U	71.SB400.D0U (ver A13)
U32	clock gen.	71.00137.C0W	71.00137.C0W

U70	VGA M52	71.0M52P.A0U	
U64	VRAM FOR M52		
U65	VRAM FOR M52		
U69	VRAM FOR M52		
U71	VRAM FOR M52		

U66	BIOS SOCKET	72.39040.G03	62.10002.032 (NO NEED WHEN PD)
U66	BIOS IC	72.39040.G03	72.39040.H03 (DIP STAGE IN LAB, SMT IN PD)

U75	GIGA LAN	71.08110.00G	71.08110.A0G
U75	10/100 LAN	71.08110.00G	71.08100.C0G

<Variant Name>



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Title

HISTORY

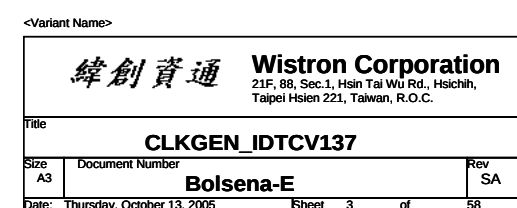
Size
A3

Document Number
Bolsena-E

Rev
SA

Date: Thursday, October 13, 2005

Sheet 2 of 58



HTT for CPU sideA
Transmit power
and NB sideA Receive
power

HTT for CPU sideB
Receive power
and NB sideA
Transmit power

LAYOUT: Place bypass cap on topside of board near
HTT power pins that are not connected directly to
downstream HTT device, but connected internally to
other HTT power pins.

Used SideB Power Plane

Used SideA Power Plane

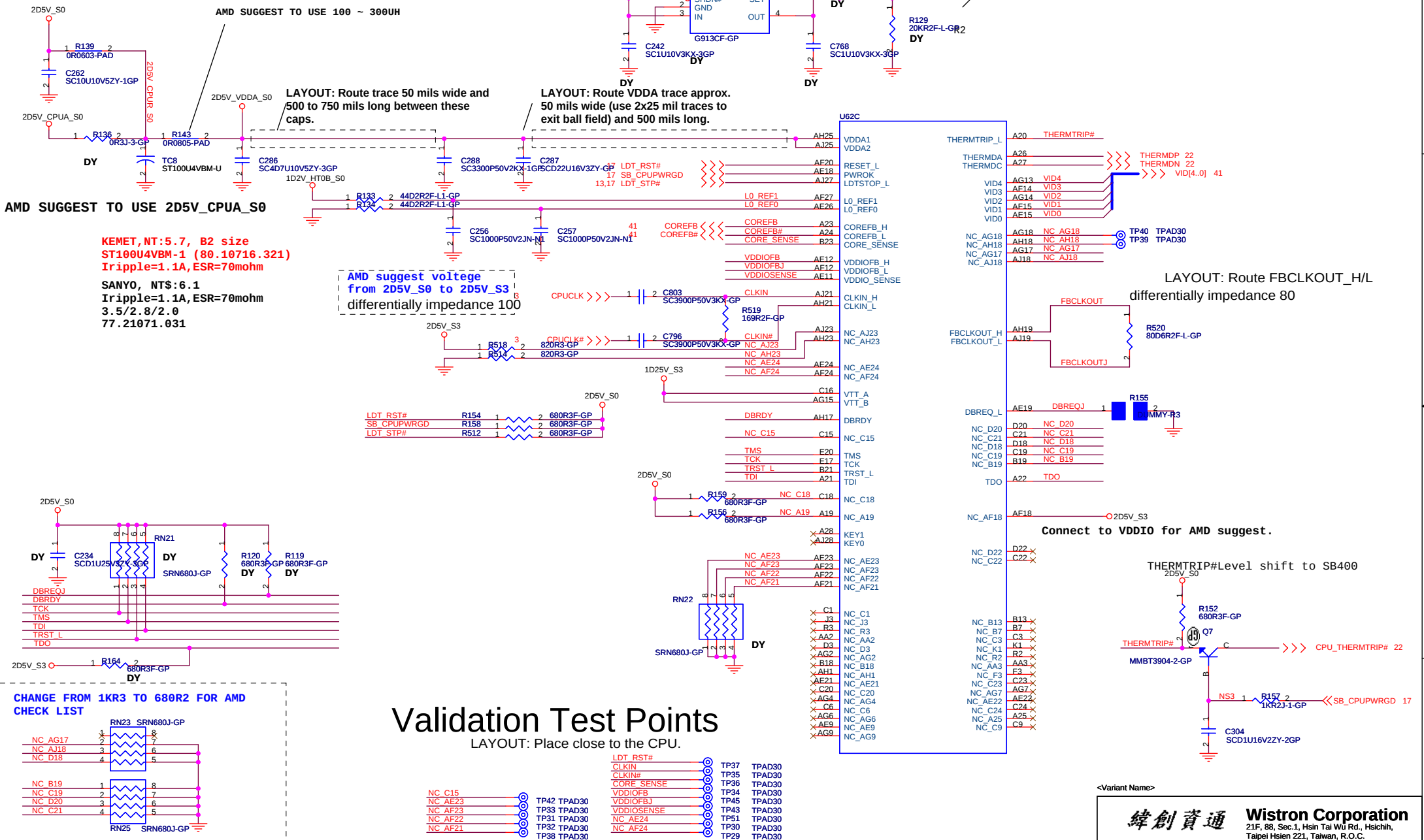
ME : 62.10055.121
2nd:62.10055.101

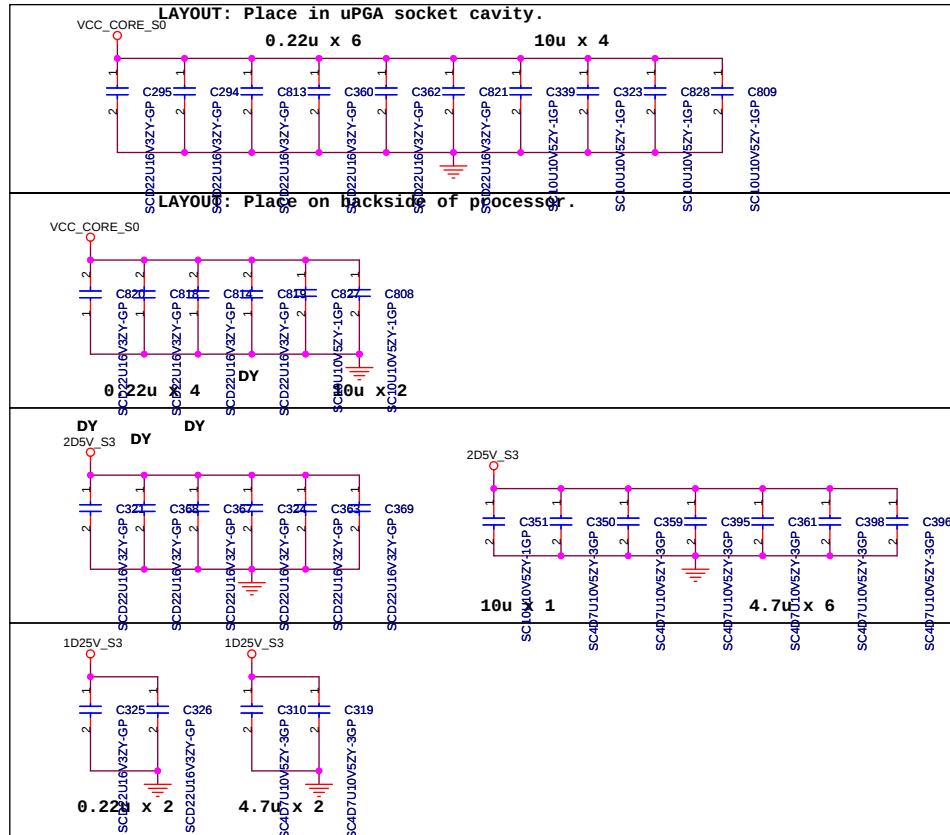
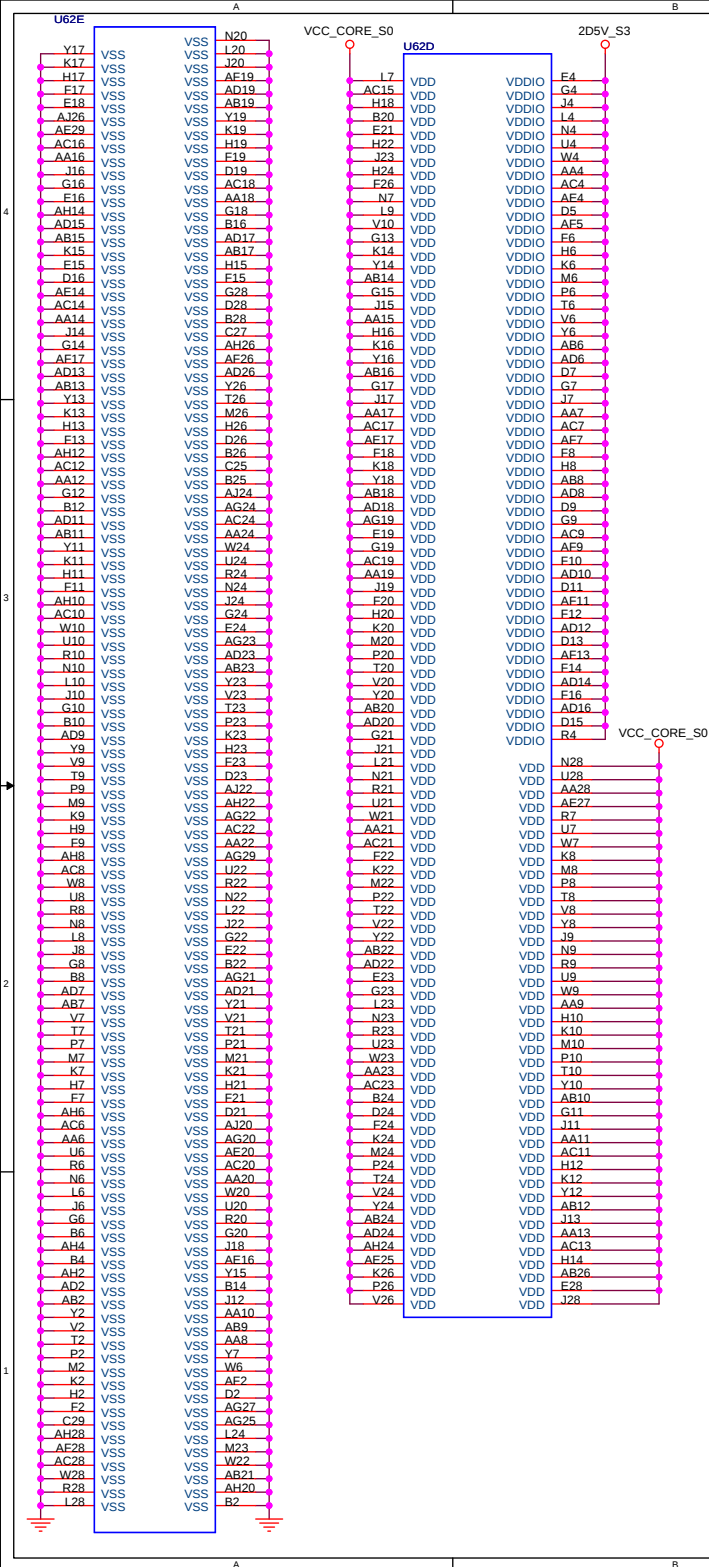
<Variant Name>

緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

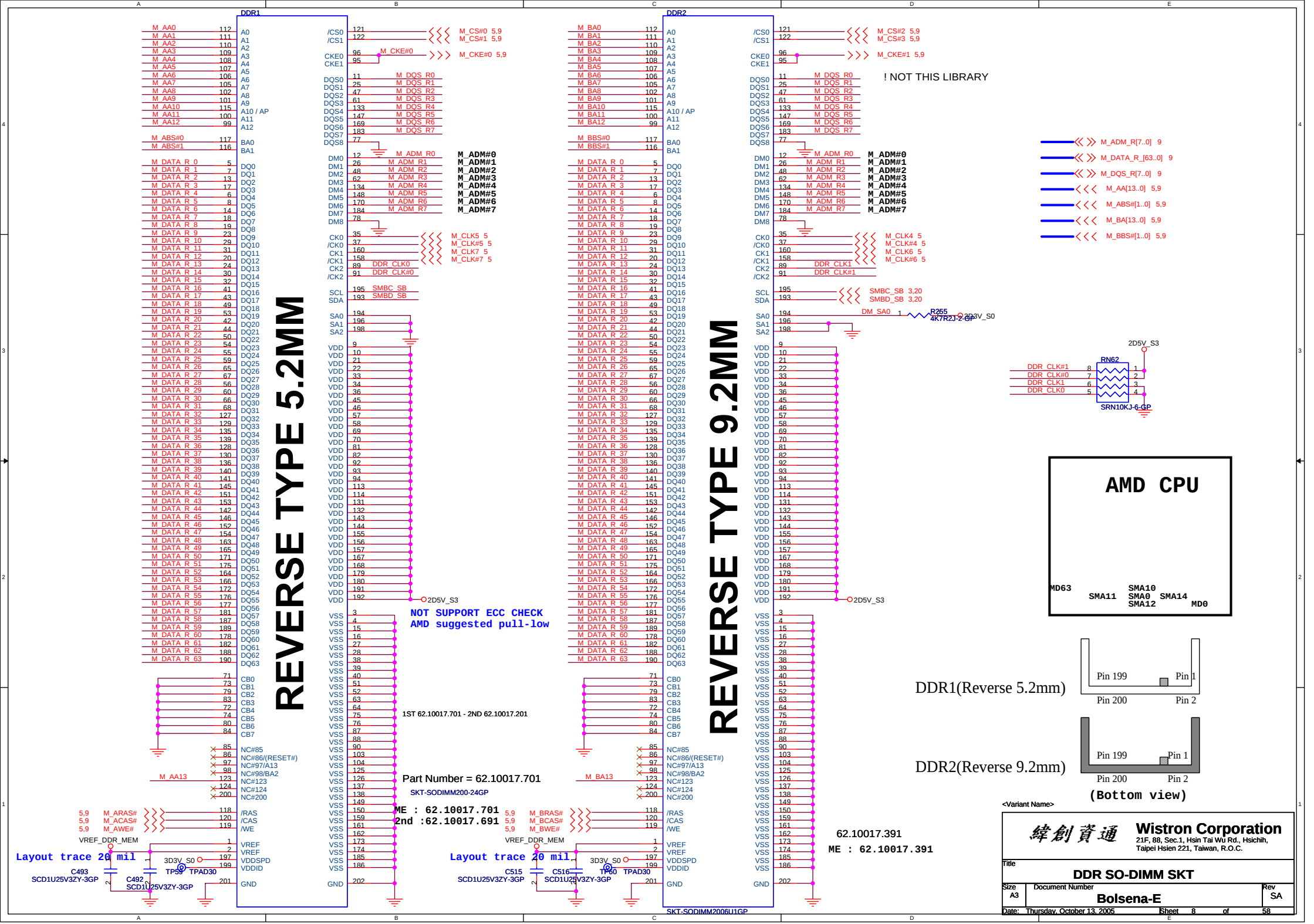
Title			CPU(1/4)_HyperTransport I/F	
Size	Document Number		Rev	
A3	Bolsena-E		SA	
Date: Thursday, October 13, 2005		Sheet	4	of 58

2D5V_VDDA_S0



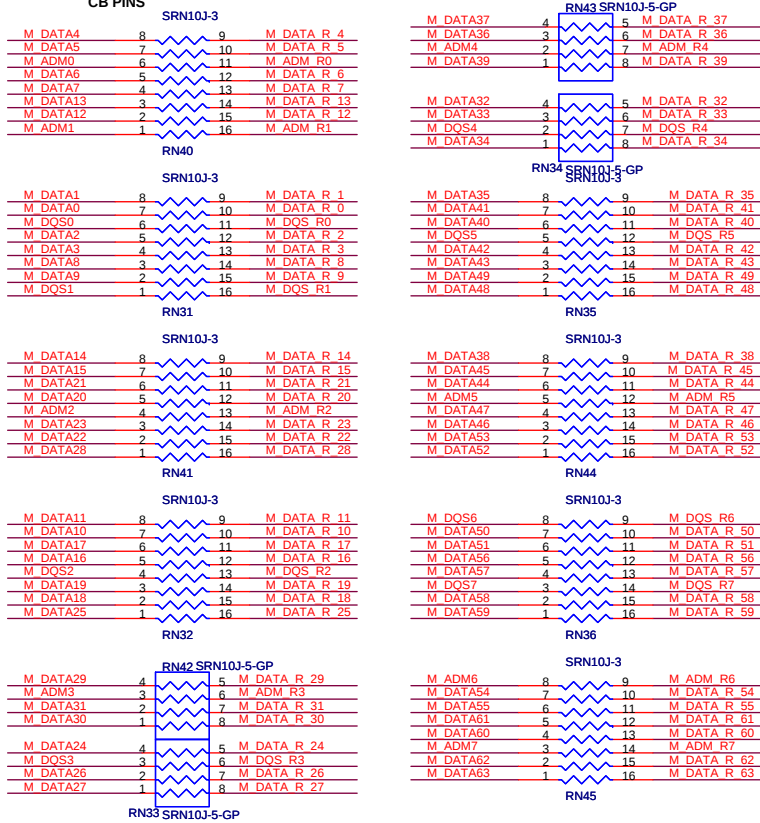


<Variant Name>



SERIES DAMPING

PLACE RNs CLOSE TO FIRST DIMM, < 0.75"
STRICT EQUAL LENGTH LIMITATION WITH DQS,
CB PINS



PARALLEL TERMINATION

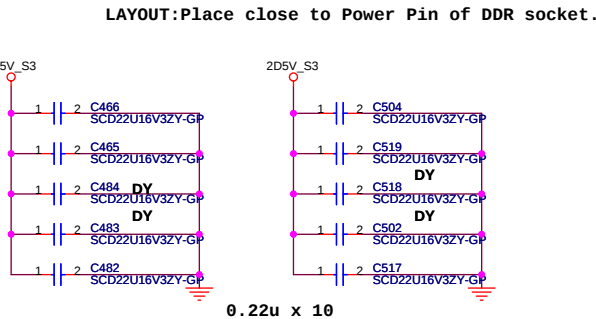
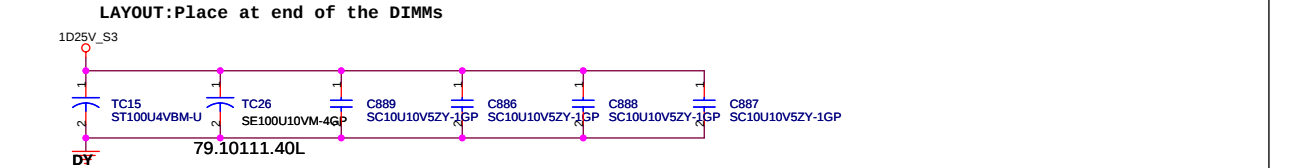
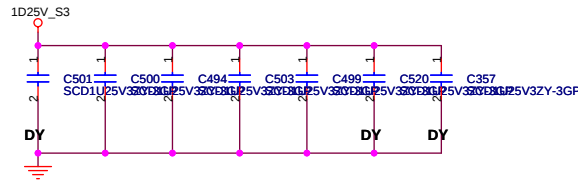
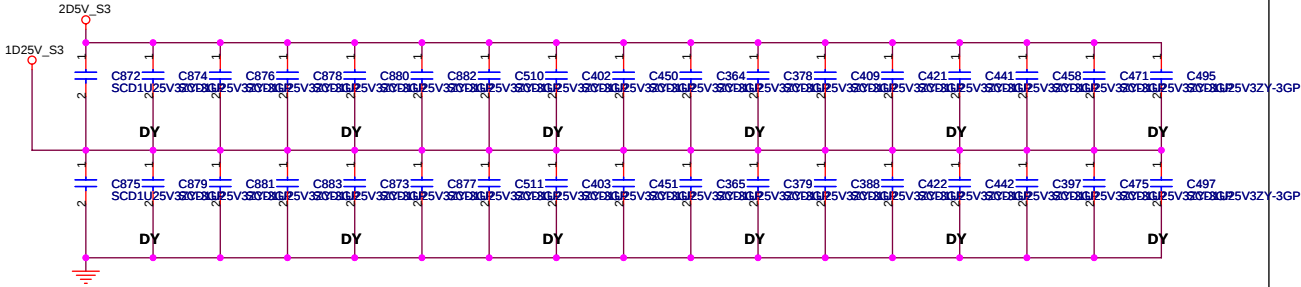
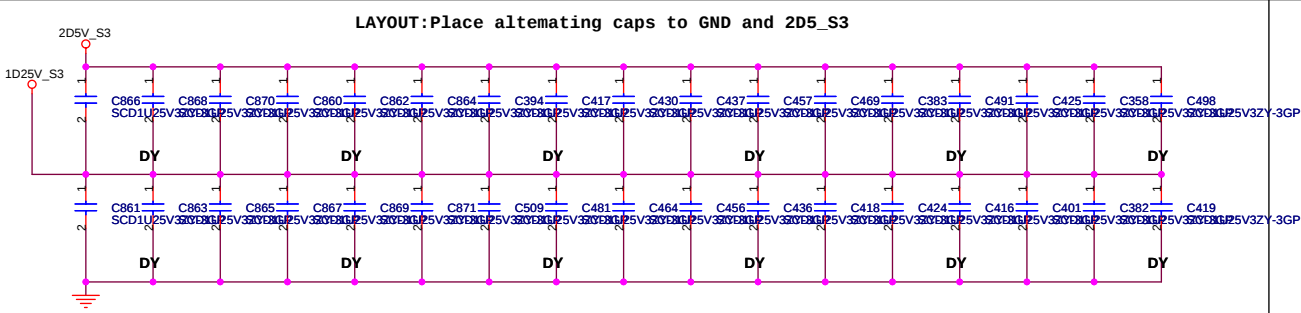
PULL HIGH STUBS < 0.8", PLACE RPs CLOSE TO SECOND DM (DM2)
NO EQUAL LENGTH LIMITATION



05/10
Remove the damping resistor for AMD suggest.

<Variant Name>

Title		Wistron Corporation	
Size A3		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Document Number		Bolsena-E	
Date: Thursday, October 13, 2005	Sheet 9	of	58

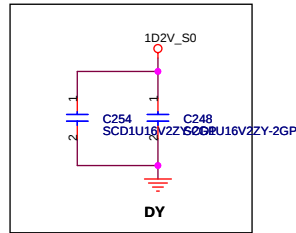


CLAW HAMMER TO NB

NB TO CLAW HAMMER

4 CPUCADOUT[15..0] >>>>
4 CPUCADOUTJ[15..0] >>>>

>>>> NB0CADOUT[15..0] 4
>>>> NB0CADOUTJ[15..0] 4



AROUND NB

1D2V_S0

CPUCADOUT15 T26 HT_RXCAD15P
CPUCADOUTJ15 R26 HT_RXCAD15N
CPUCADOUT14 U25 HT_RXCAD14P
CPUCADOUTJ14 U24 HT_RXCAD14N
CPUCADOUT13 V26 HT_RXCAD13P
CPUCADOUTJ13 U26 HT_RXCAD13P
CPUCADOUT12 W25 HT_RXCAD12P
CPUCADOUTJ12 W24 HT_RXCAD12N
CPUCADOUT11 AA25 HT_RXCAD11P
CPUCADOUTJ11 AA24 HT_RXCAD11N
CPUCADOUT10 AB26 HT_RXCAD10P
CPUCADOUTJ10 AA26 HT_RXCAD10N
CPUCADOUT9 AC25 HT_RXCAD9P
CPUCADOUTJ9 AC24 HT_RXCAD9N
CPUCADOUT8 AD26 HT_RXCAD8P
CPUCADOUTJ8 AC26 HT_RXCAD8N

CPUCADOUT7 R29 HT_RXCAD7P
CPUCADOUTJ7 R28 HT_RXCAD7N
CPUCADOUT6 T30 HT_RXCAD6P
CPUCADOUTJ6 R30 HT_RXCAD6N
CPUCADOUT5 T28 HT_RXCAD5P
CPUCADOUTJ5 T29 HT_RXCAD5N
CPUCADOUT4 V29 HT_RXCAD4P
CPUCADOUTJ4 U29 HT_RXCAD4P
CPUCADOUT3 Y30 HT_RXCAD4N
CPUCADOUTJ3 W30 HT_RXCAD3P
CPUCADOUT2 Y28 HT_RXCAD2P
CPUCADOUTJ2 Y29 HT_RXCAD2N
CPUCADOUT1 AB29 HT_RXCAD1P
CPUCADOUTJ1 AA29 HT_RXCAD1N
CPUCADOUT0 AC29 HT_RXCAD0P
CPUCADOUTJ0 AC28 HT_RXCAD0N

U61A

PART 10F6

HYPER TRANSPORT CPU I/F

HT_TXCAD15P R24 NB0CADOUT15
HT_TXCAD15N R25 NB0CADOUTJ15
HT_TXCAD14P N26 NB0CADOUT14
HT_TXCAD14N P26 NB0CADOUTJ14
HT_TXCAD13P N24 NB0CADOUT13
HT_TXCAD13N N25 NB0CADOUTJ13
HT_TXCAD12P L26 NB0CADOUT12
HT_TXCAD12N M26 NB0CADOUTJ12
HT_TXCAD11P J26 NB0CADOUT11
HT_TXCAD11N K26 NB0CADOUTJ11
HT_TXCAD10P J24 NB0CADOUT10
HT_TXCAD10N J25 NB0CADOUTJ10
HT_TXCAD9P G26 NB0CADOUT9
HT_TXCAD9N H26 NB0CADOUTJ9
HT_TXCAD8P G24 NB0CADOUT8
HT_TXCAD8N G25 NB0CADOUTJ8

HT_TXCAD7P L30 NB0CADOUT7
HT_TXCAD7N M30 NB0CADOUTJ7
HT_TXCAD6P L28 NB0CADOUT6
HT_TXCAD6N L29 NB0CADOUTJ6
HT_TXCAD5P J29 NB0CADOUT5
HT_TXCAD5N K29 NB0CADOUTJ5
HT_TXCAD4P H30 NB0CADOUT4
HT_TXCAD4N H29 NB0CADOUTJ4
HT_TXCAD3P E29 NB0CADOUT3
HT_TXCAD3N E28 NB0CADOUTJ3
HT_TXCAD2P D30 NB0CADOUT2
HT_TXCAD2N E30 NB0CADOUTJ2
HT_TXCAD1P D28 NB0CADOUT1
HT_TXCAD1N D29 NB0CADOUTJ1
HT_TXCAD0P B29 NB0CADOUT0
HT_TXCAD0N C29 NB0CADOUTJ0

4 CPUHTCLKOUT1 >>>> CPUHTCLKOUT1 Y26 HT_RXCLK1P
4 CPUHTCLKOUTJ1 >>>> CPUHTCLKOUTJ1 W26 HT_RXCLK1N

4 CPUHTCLKOUT0 >>>> CPUHTCLKOUT0 W29 HT_RXCLK0P
4 CPUHTCLKOUTJ0 >>>> CPUHTCLKOUTJ0 W28 HT_RXCLK0N

4 CPUHTTCTLOUT0 >>>> CPUHTTCTLOUT0 P29 HT_RXCTLN
4 CPUHTTCTLOUTJ0 >>>> CPUHTTCTLOUTJ0 N29 HT_RXCTLN

HT_TXCLK1P L24 NB0HTTCLKOUT1 >>>> NB0HTTCLKOUT1 4
HT_TXCLK1N L25 NB0HTTCLKOUTJ1 >>>> NB0HTTCLKOUTJ1 4

HT_TXCLK0P E29 NB0HTTCLKOUT0 >>>> NB0HTTCLKOUT0 4
HT_TXCLK0N G29 NB0HTTCLKOUTJ0 >>>> NB0HTTCLKOUTJ0 4

HT_TXCTLN M29 NB0HTTCTLOUT >>>> NB0HTTCTLOUT 4
HT_TXCTLN M28 NB0HTTCTLOUTJ >>>> NB0HTTCTLOUTJ 4

HT_TXCALP R28 HT_TXCALP 1 R498 2 100R2F-L1-GP-U
HT_TXCALN A28 HT_TXCALN

<Variant Name>

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Title

ATI-RS482M (1 of 4) HT

Size
A3

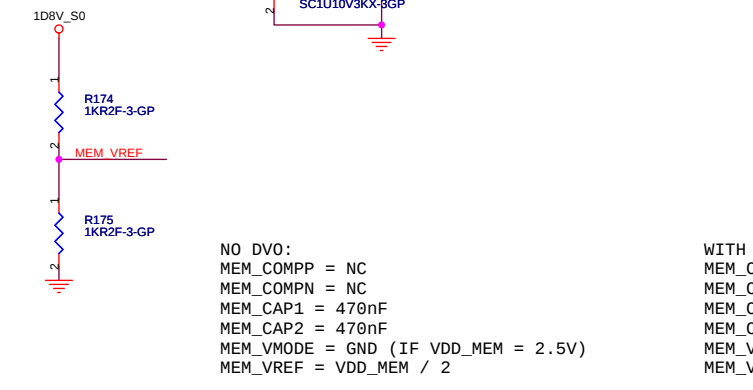
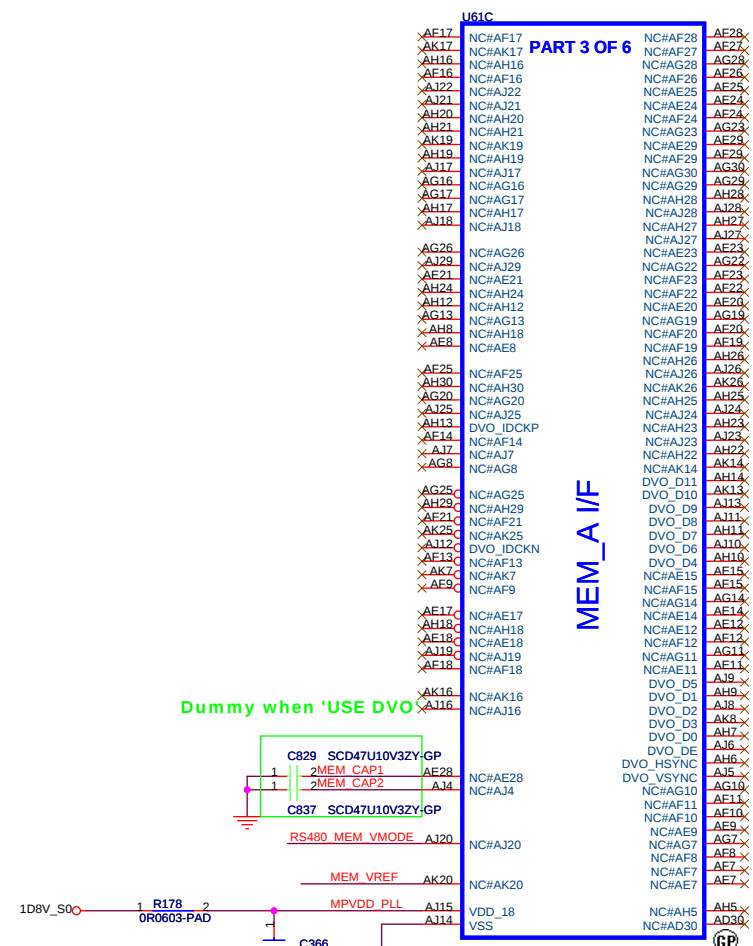
Document Number

Bolsena-E

Rev
SA

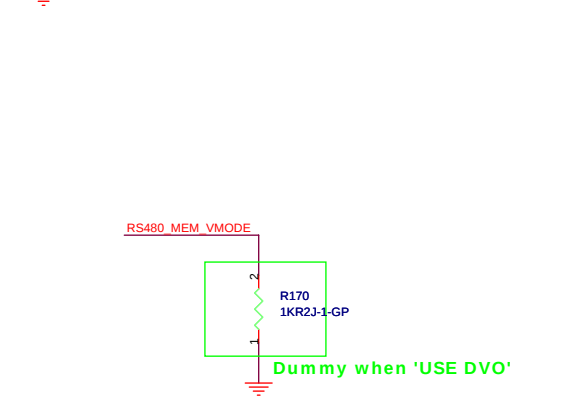
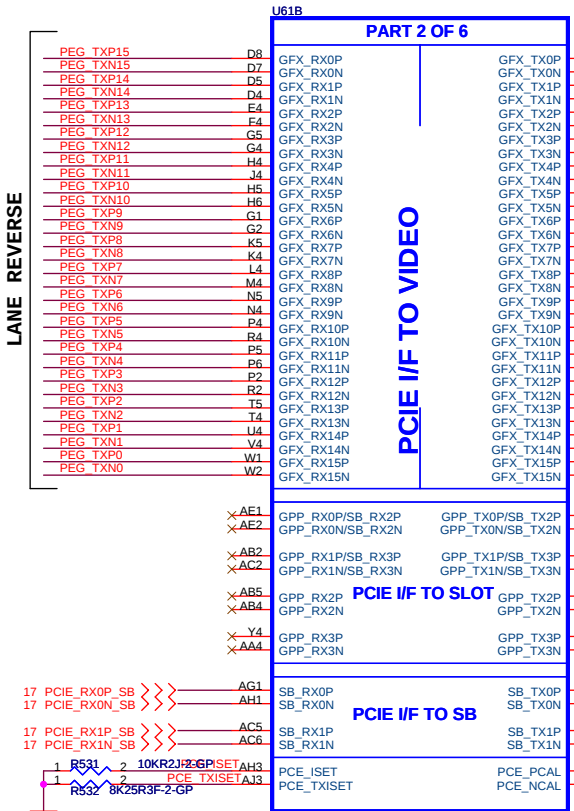
Date: Thursday, October 13, 2005

Sheet 11 of 58

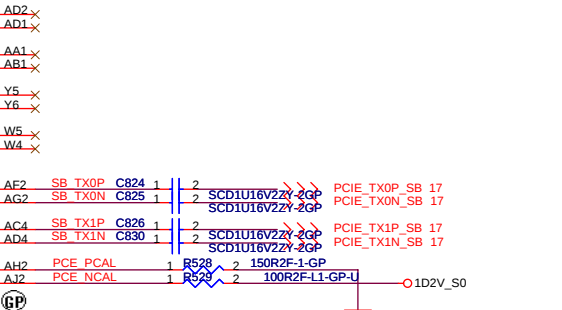
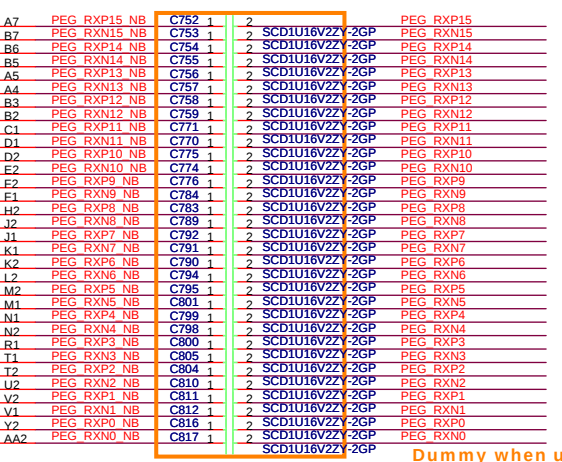


NO DVO:
MEM_COMP = NC
MEM_COMPN = NC
MEM_CAP1 = 470nF
MEM_CAP2 = 470nF
MEM_VMODE = GND (IF VDD_MEM = 2.5V)
MEM_VREF = VDD_MEM / 2

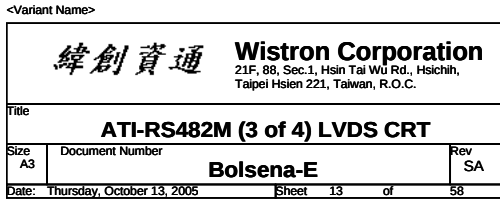
WITH DVO:
MEM_COMP = 61.9 OHM TO GND
MEM_COMPN = 61.9 OHM TO VDD_MEM
MEM_CAP1 = NC
MEM_CAP2 = NC
MEM_VMODE = 1.8V (IF VDD_MEM = 1.8V)
MEM_VREF = VDD_MEM / 2

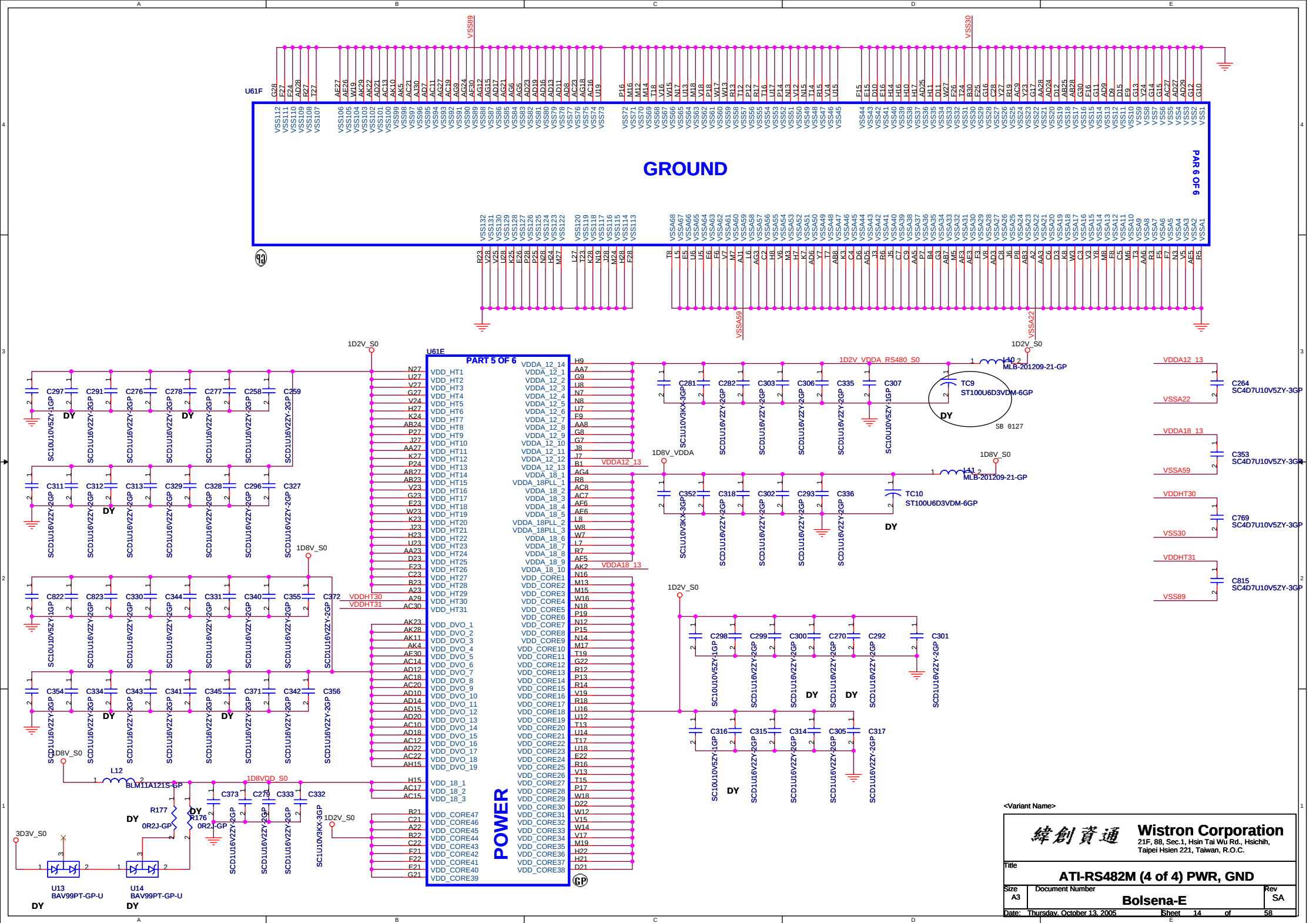


Dummy when 'USE DVO'



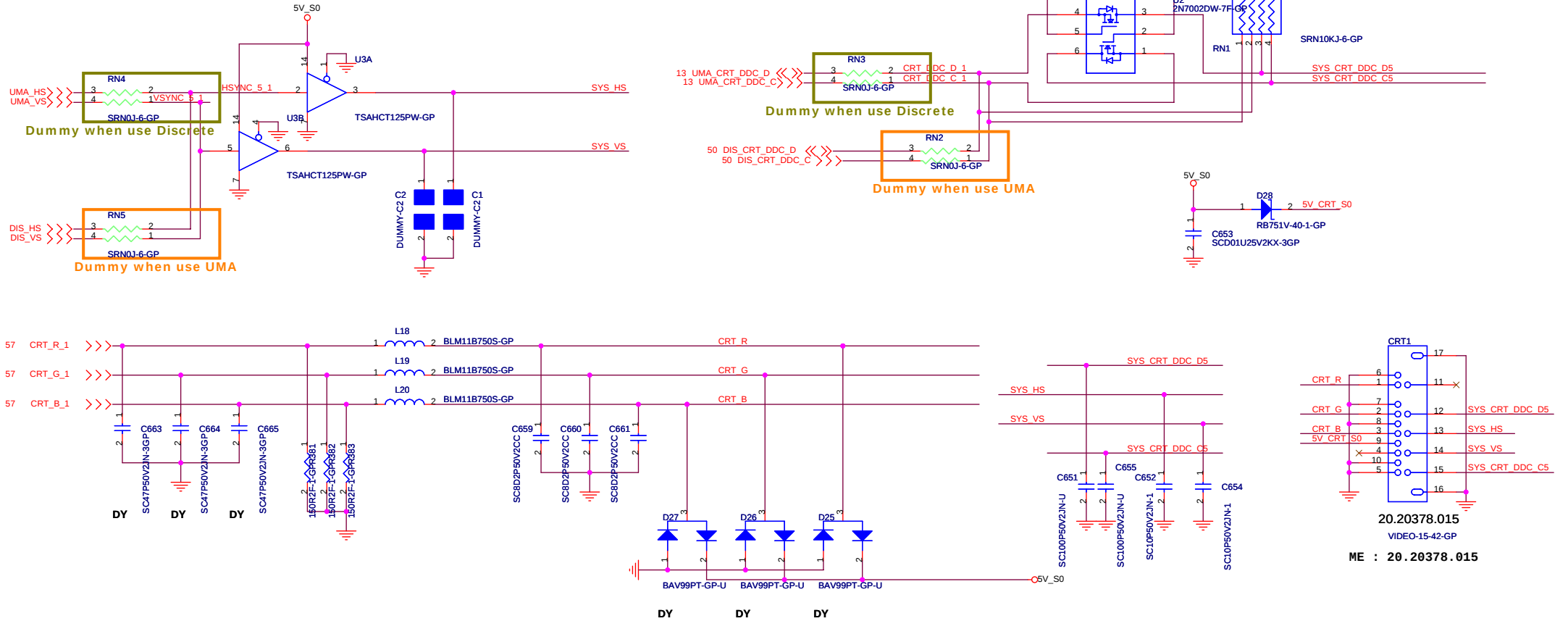
Dummy when use UMA



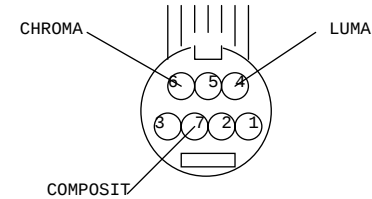
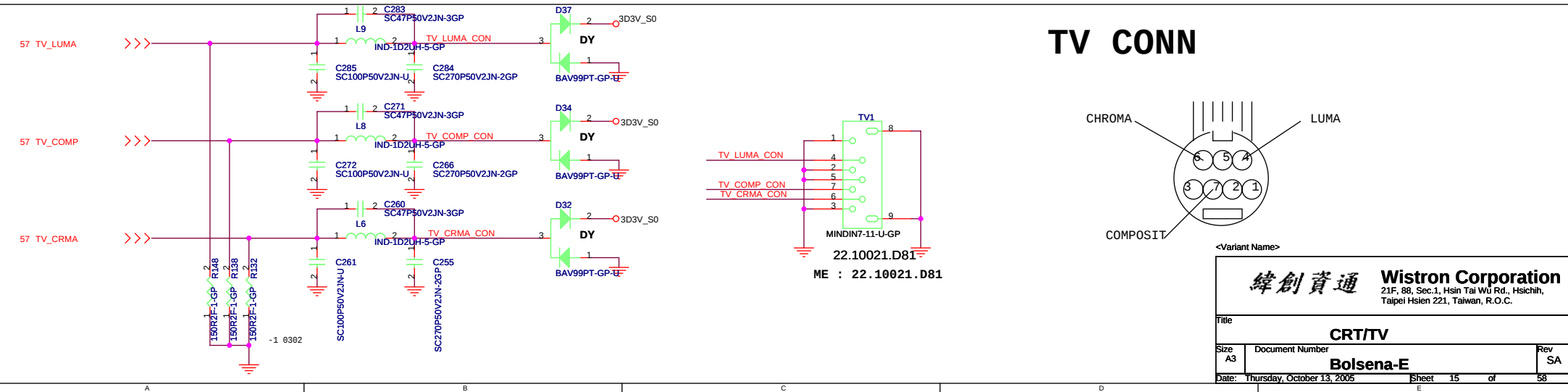


CRT CONN

200mA Rating/Spec 500mA

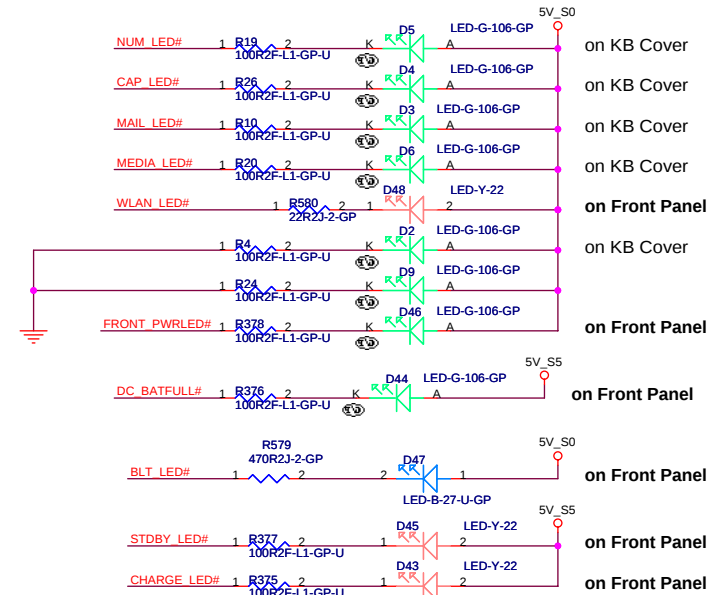
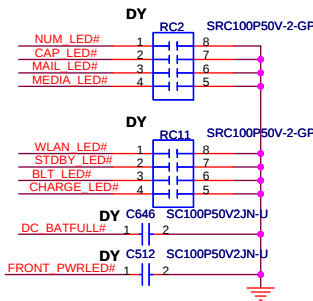
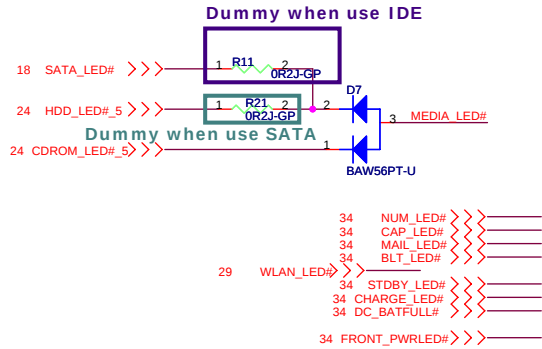


TV CONN

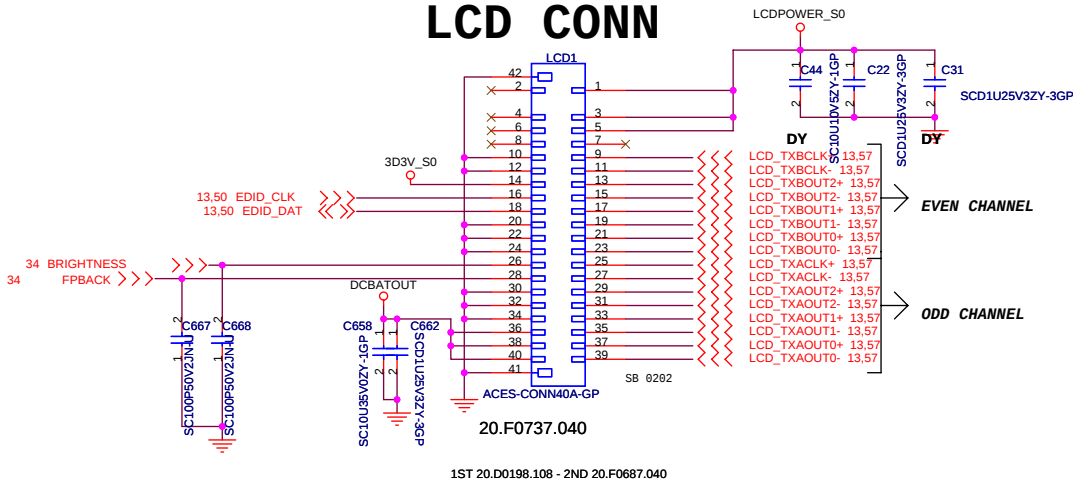


Title		
CRT/TV		
Size A3	Document Number	Rev SA
Bolsena-E		
Date: Thursday, October 13, 2005	Sheet 15 of 58	

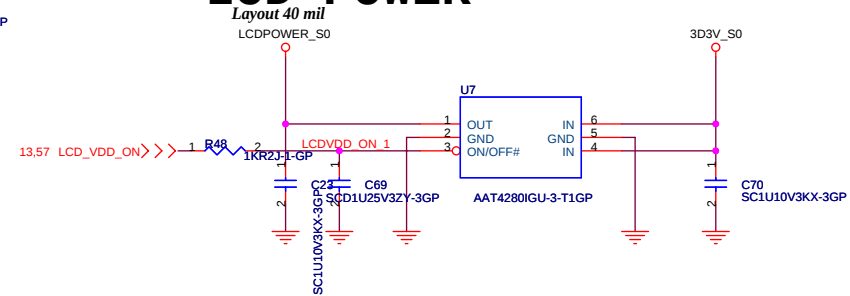
LEDs



LCD CONN



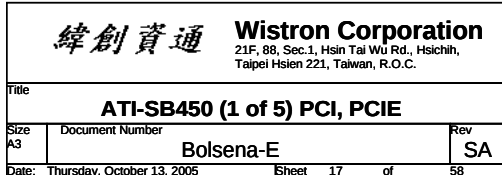
LCD POWER

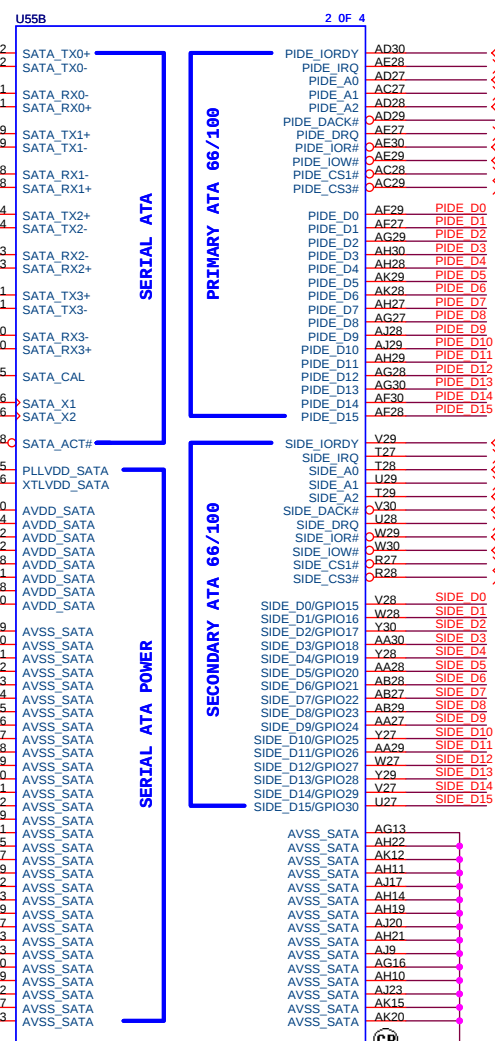
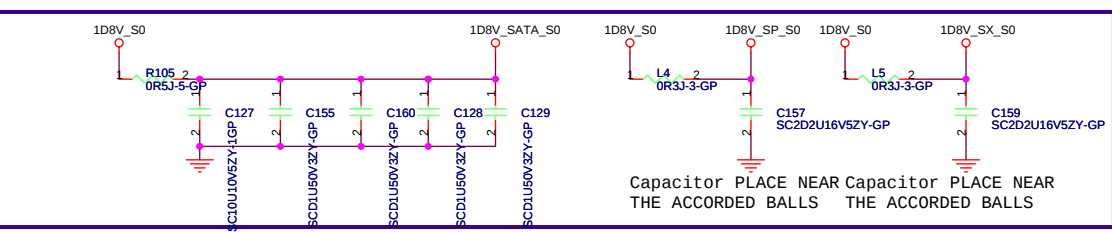
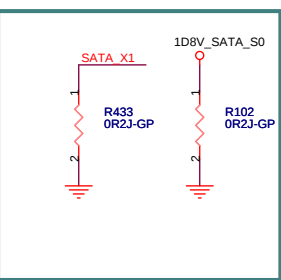
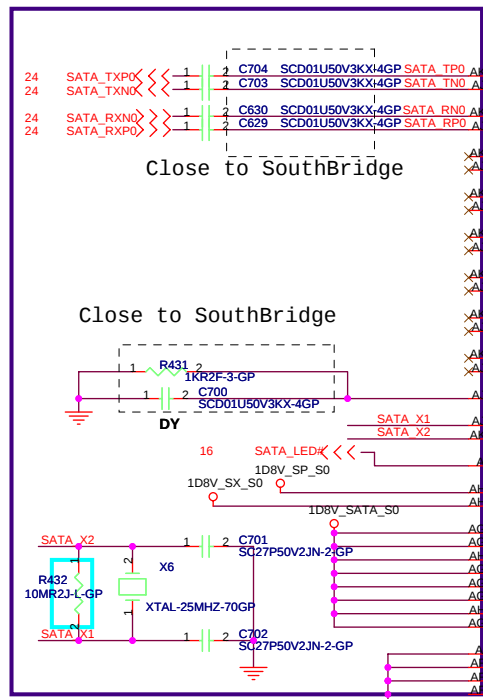


<Variant Name>

緯創資通 Wistron Corporation
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Title			LCD / LEDs	
Size	Document Number		Rev	
A3	Bolsena-E		SA	
Date:	Thursday, October 13, 2005		Sheet	16 of 58

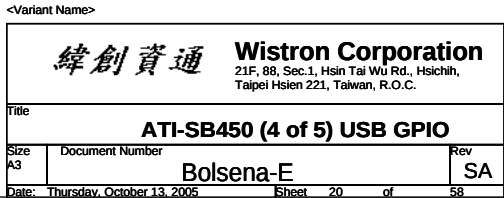


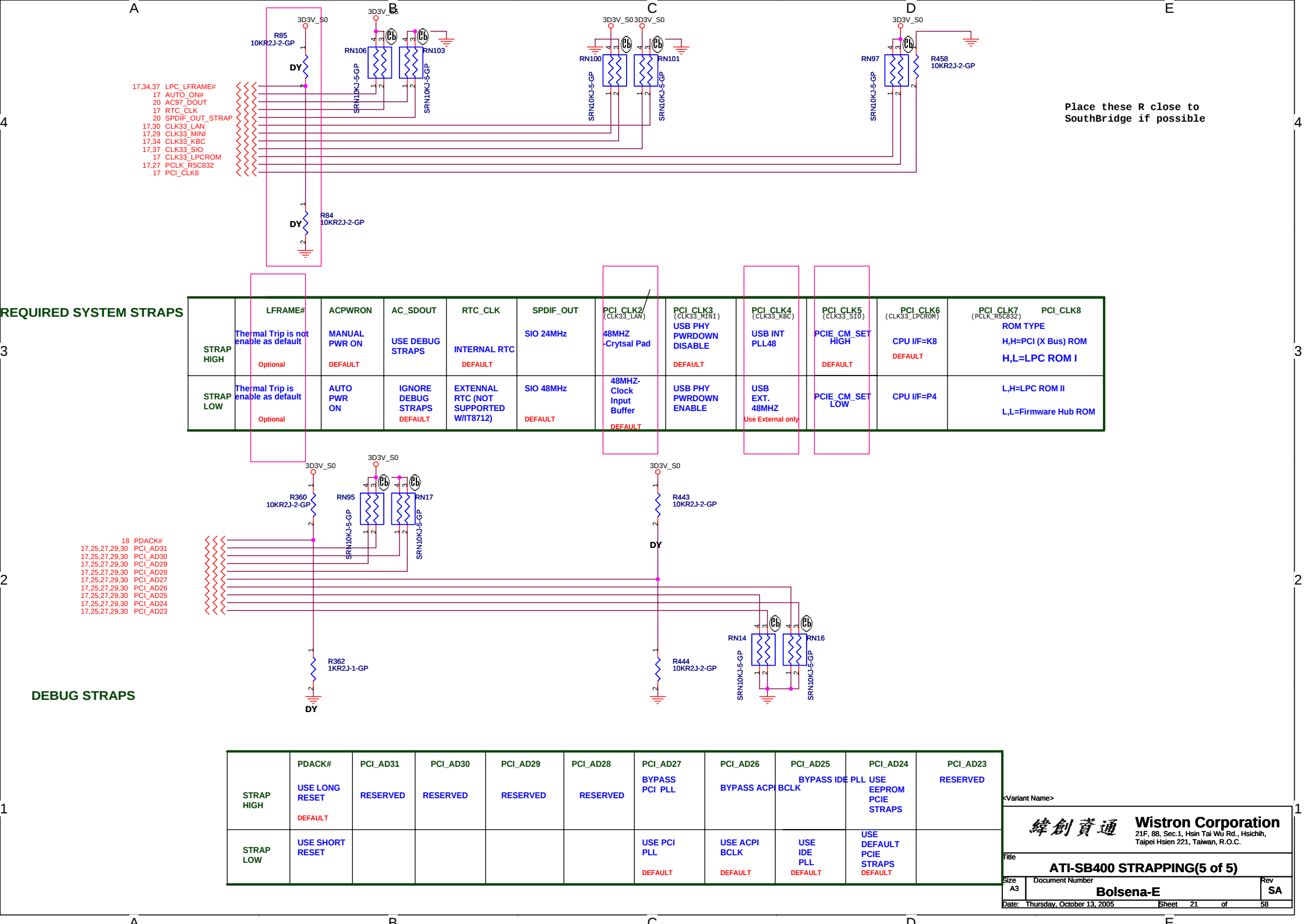


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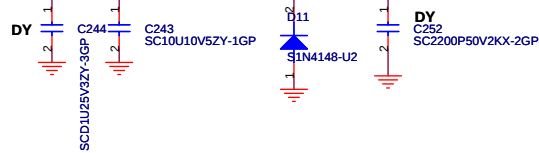


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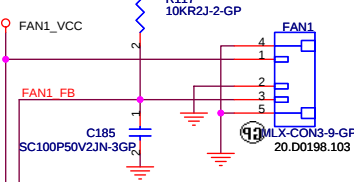




***Layout* 15 mil**

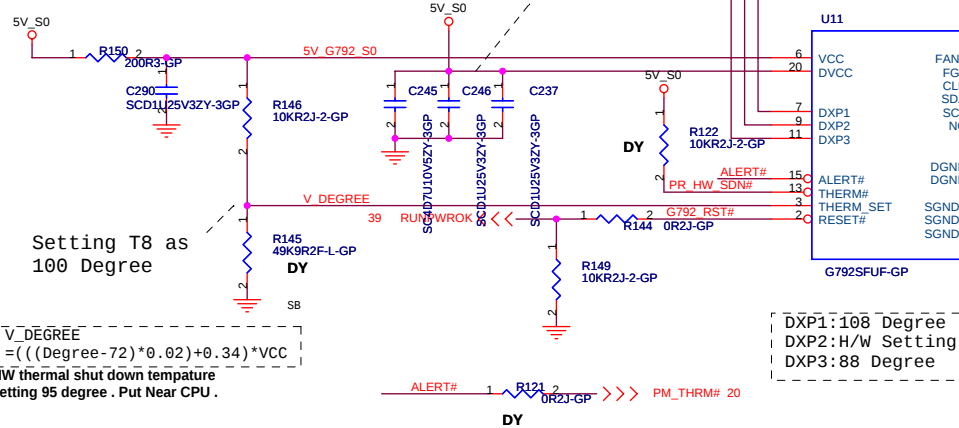


***Layout* 15 mil**



ME : 20.D0198.103
2nd: 20.F0714.003

***Layout* 30 mil**



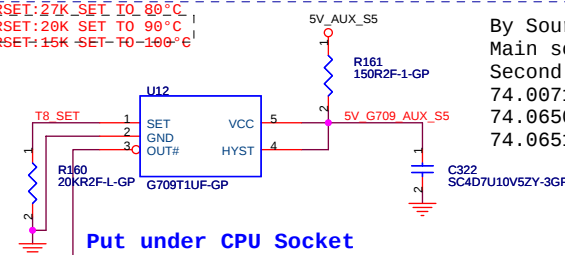
Setting T8 as
100 Degree

V_DEGREE
=(((Degree-72)*0.02)+0.34)*VCC
HW thermal shut down temperature
setting 95 degree . Put Near CPU .

DXP1:108 Degree
DXP2:H/W Setting
DXP3:88 Degree

Dummy when G792 enhanced T8 function

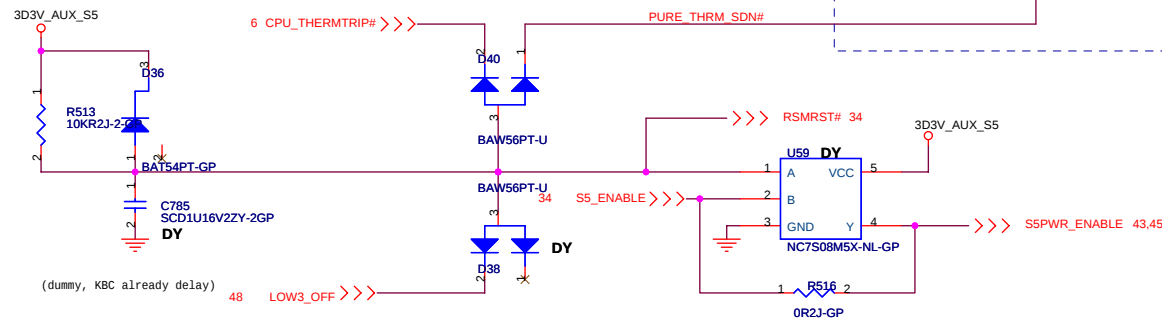
T8_RSET:27K SET TO 80°C
T8_RSET:20K SET TO 90°C
T8_RSET:15K SET TO 100°C



Put under CPU Socket

Dummy when use UMA

By Sourcer request:
Main souce 74.00709.07F
Second souce
74.00710.03P
74.06509.07F
74.06510.A7P

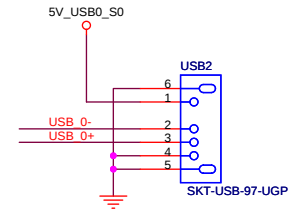
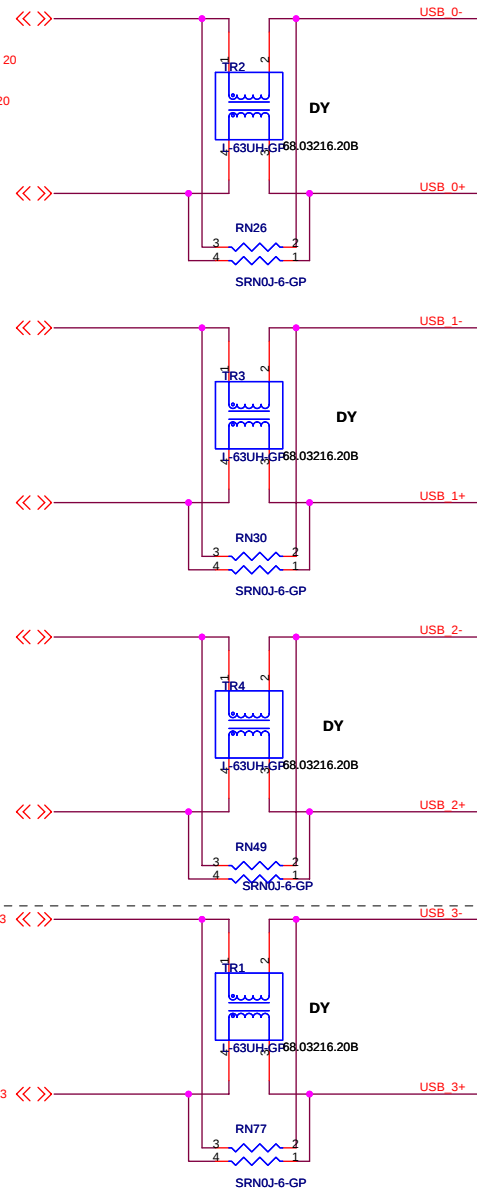
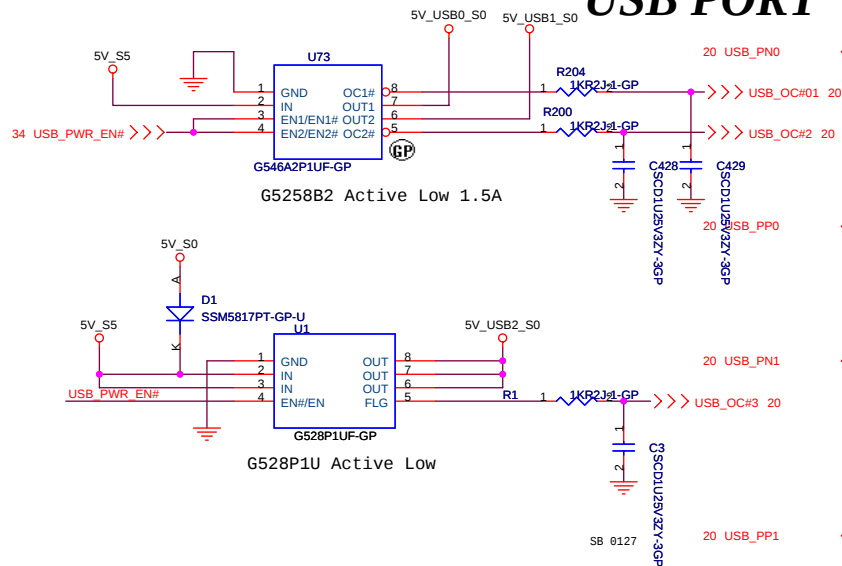
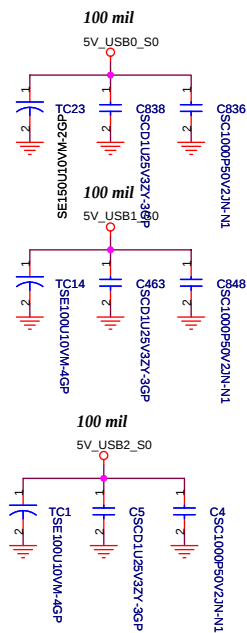


(dummy, KBC already delay)

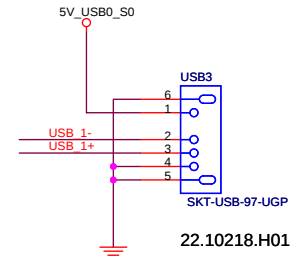
<Variant Name>

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
THERMAL G792	
Size	Document Number
Custom	Bolsena-E
Date: Thursday, October 13, 2005	Sheet 22 of 58
Rev SA	

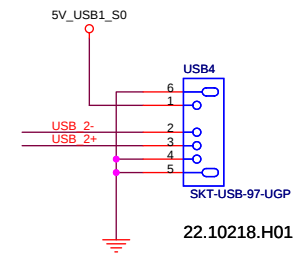
USB PORT



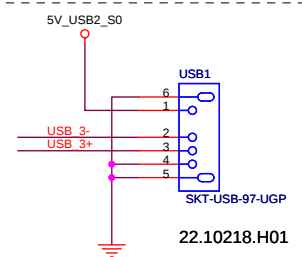
22.10218.H01



22.10218.H01



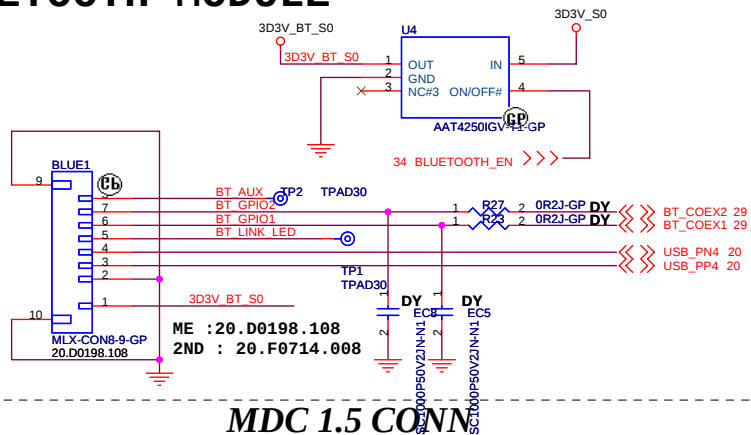
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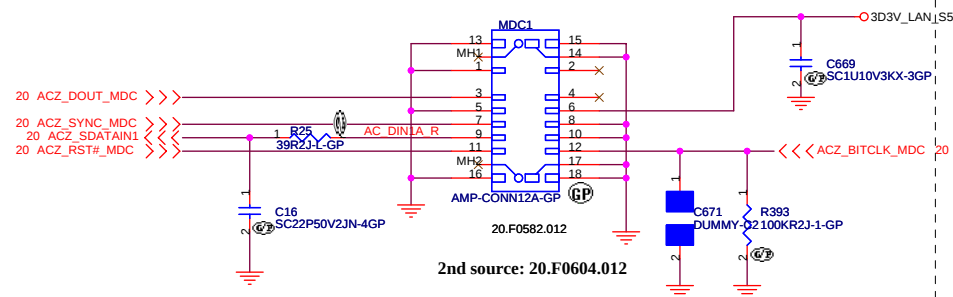
22.10218.H01

ME : 22.10218.H01
2ND : 22.10245.H11

BLUETOOTH MODULE



MDC 1.5 CONN

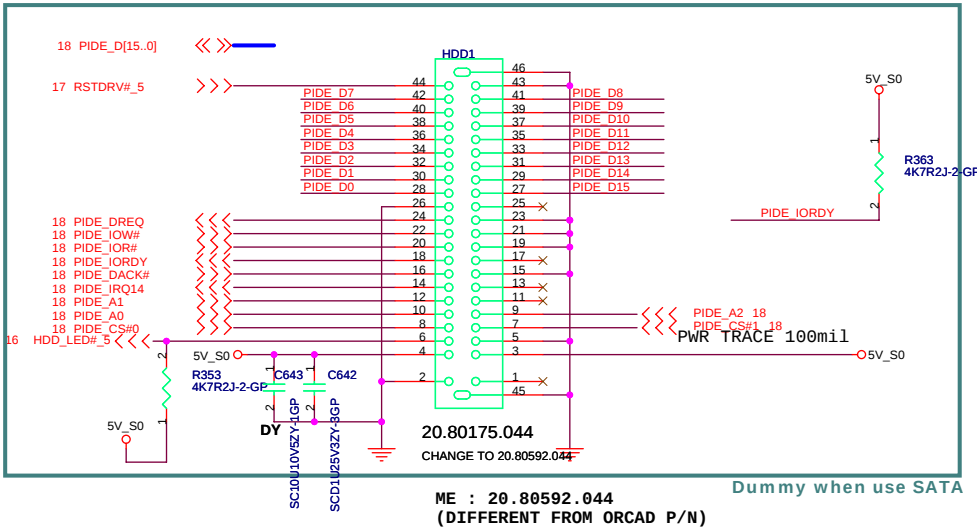


2nd source: 20.F0604.012

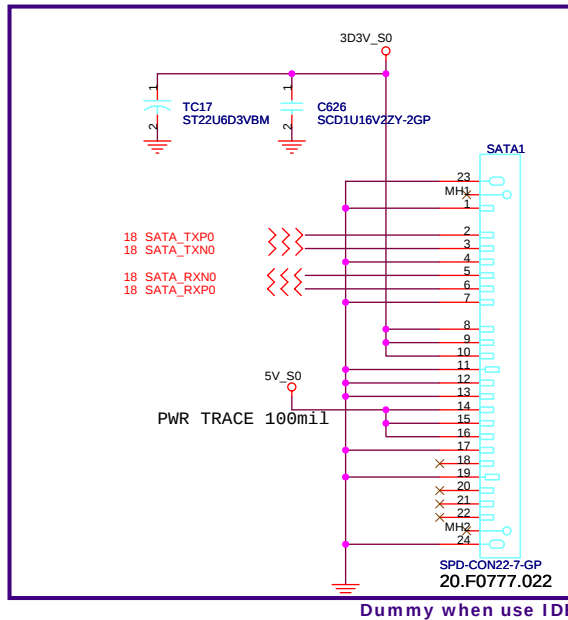
<Variant Name>

緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
USB / MDC / BLUETOOTH			
Size A3	Document Number	Rev	
Bolsena-E		SA	
Date	Thursday, October 13, 2005	Sheet	23 of 58

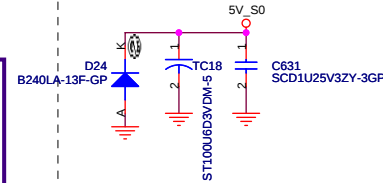
HDD



SATA Connector

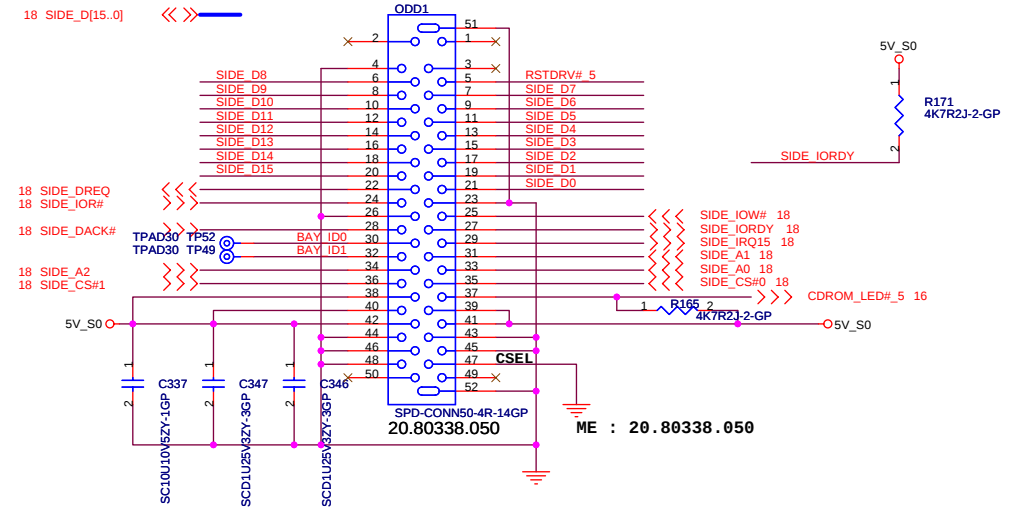


For HDD & SATA both



ME : 20.F0777.022

CDROM



<Variant Name>

緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

HDD / CDROM / SATA

Size
A3

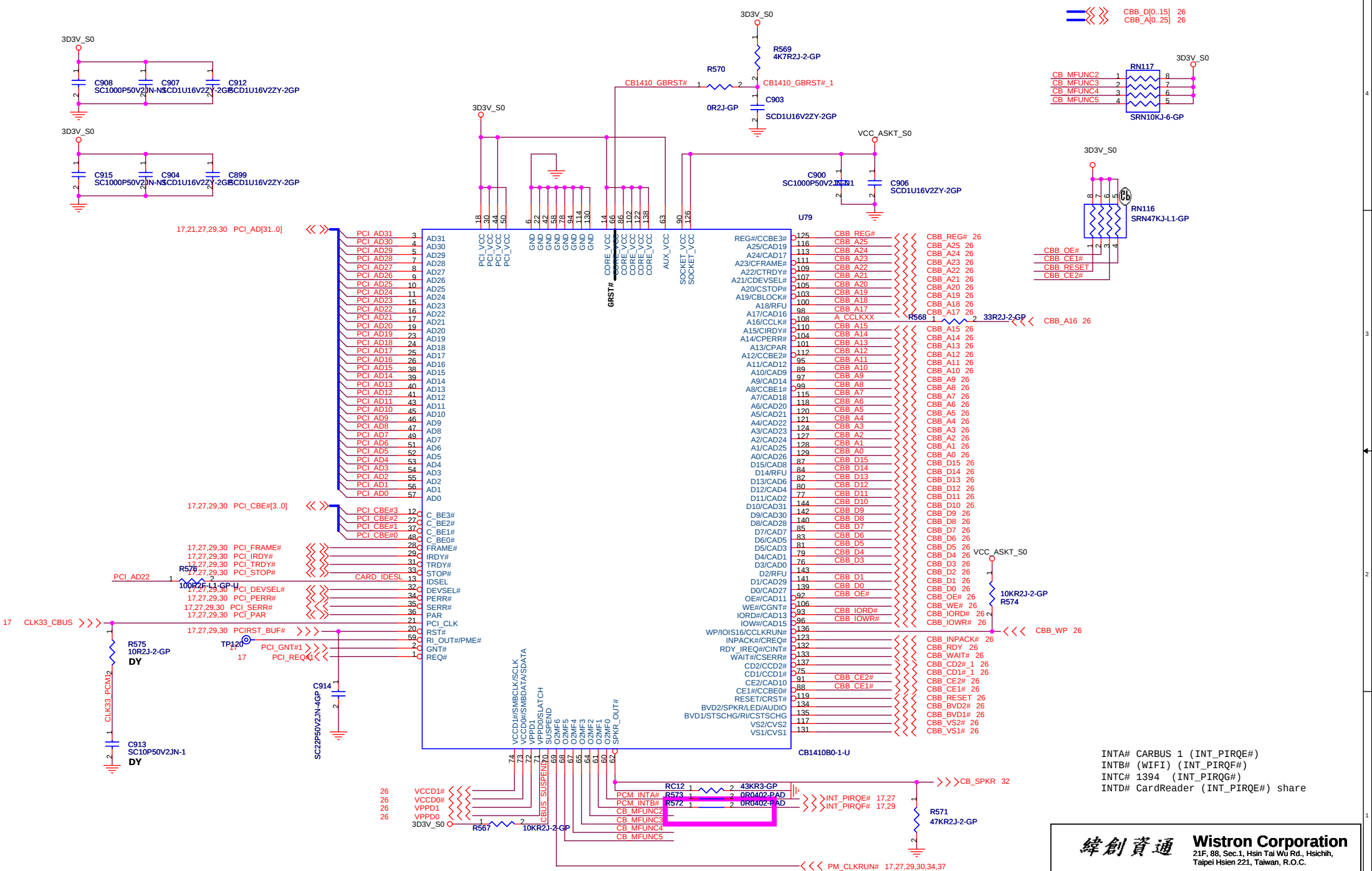
Document Number

Bolsena-E

Rev
SA

Date: Thursday, October 13, 2005

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INTA# CARBUS 1 (INT_PIRQ#)
INTB# (WIFI) (INT_PIRQ#)
INTC# 1394 (INT_PIRQ#)
INTD# CardReader (INT_PIRQ#) share

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

CardBus_ENE CB1410

Size

A3

Document Number

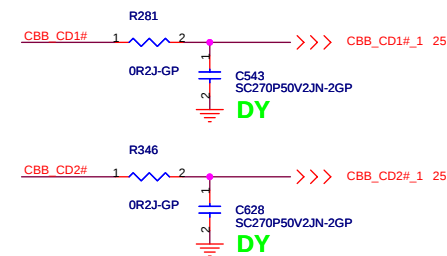
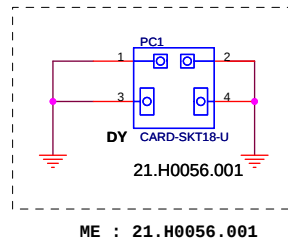
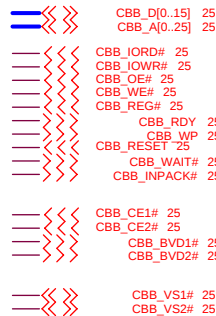
Bolsena-E

Rev

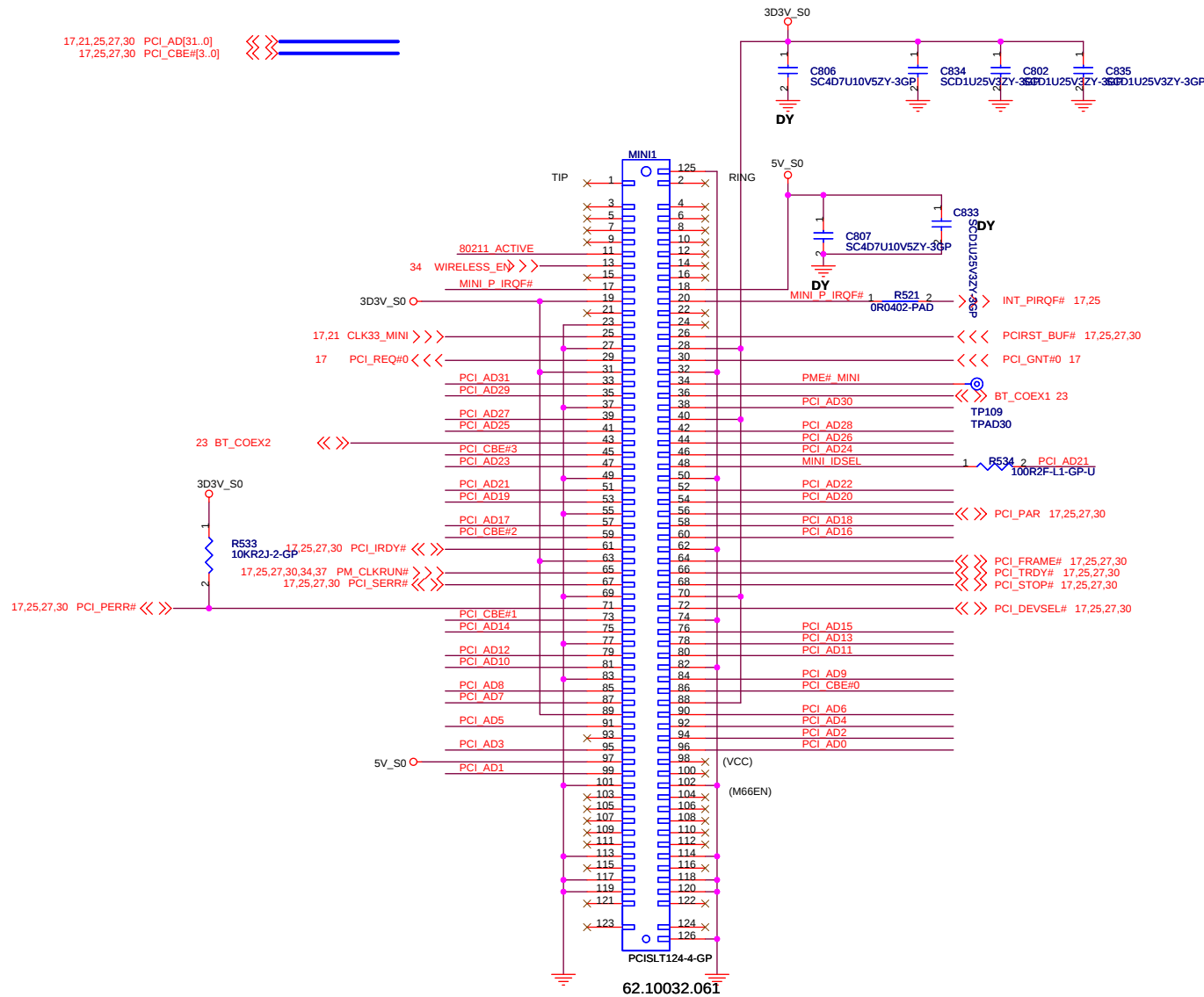
SA

Date: Thursday, October 13, 2005

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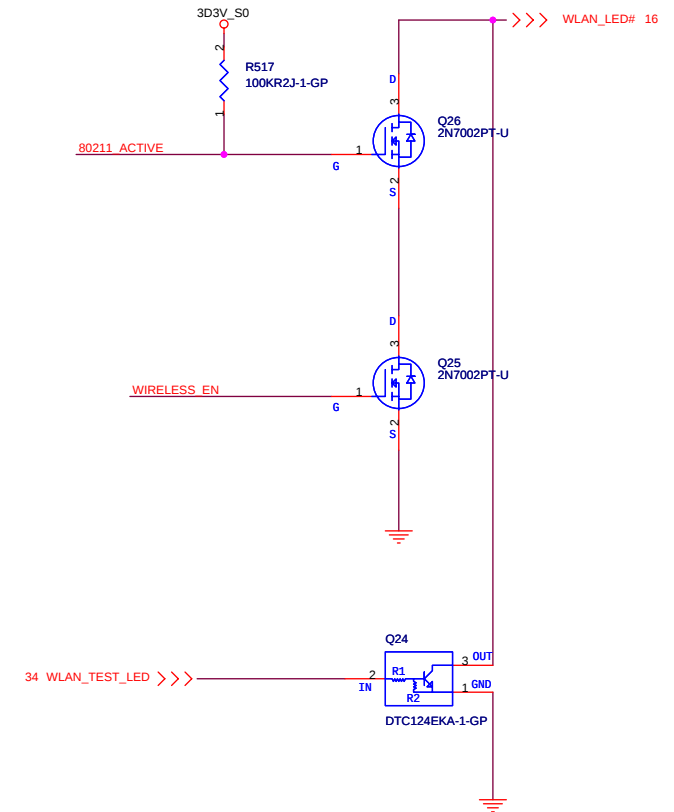
Cardbus I/F

MINI-PCI



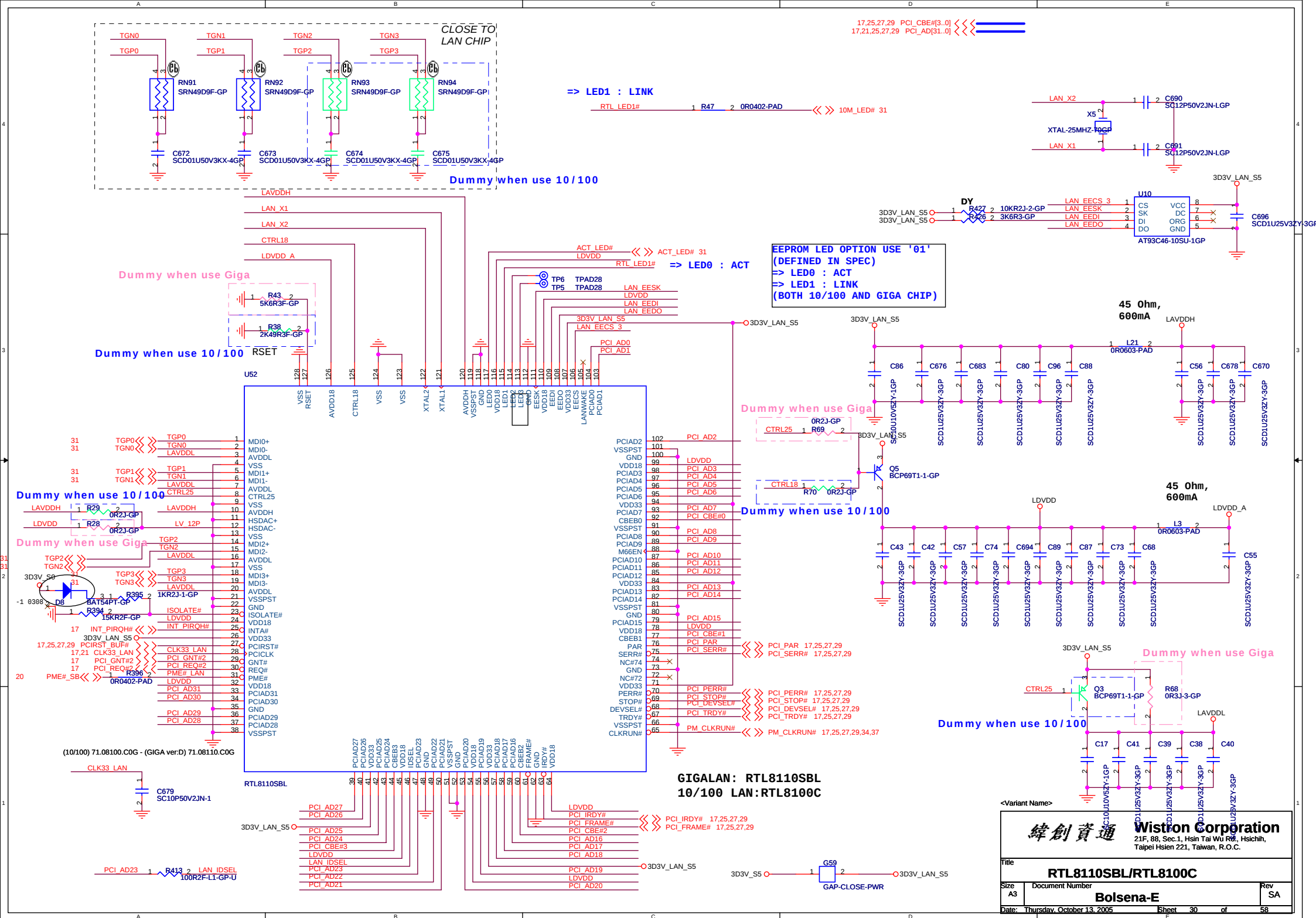
ME : 62.10032.061
2ND : 62.10043.221

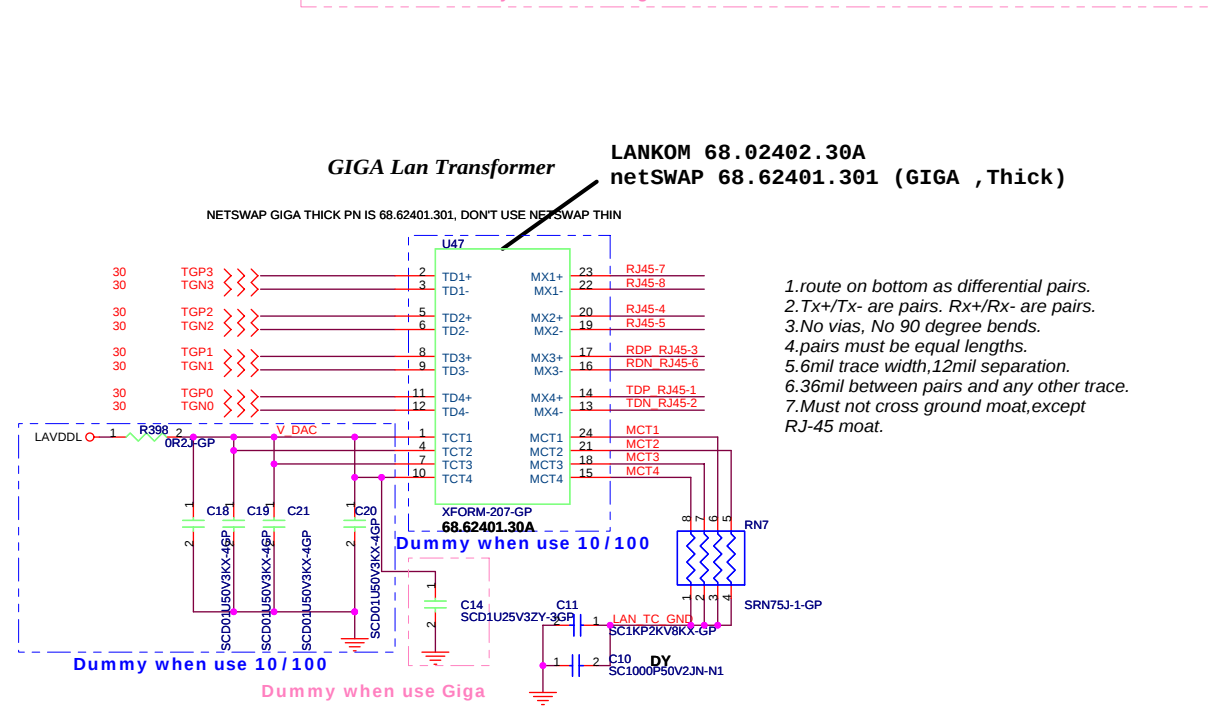
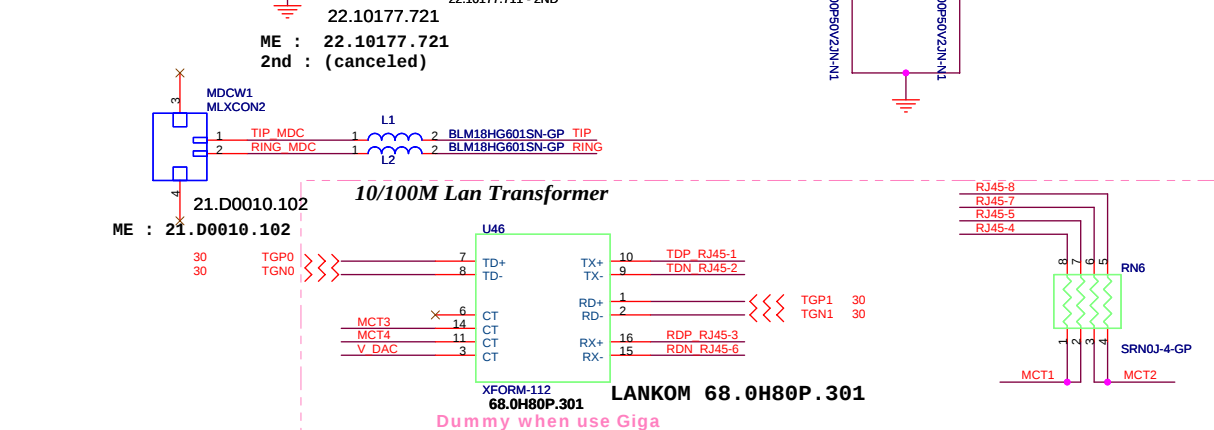
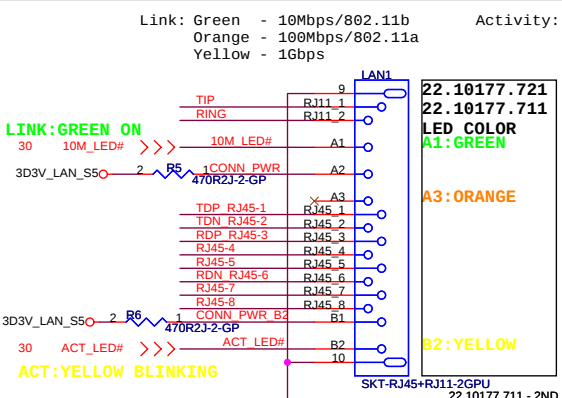
62.10032.031 - 2ND

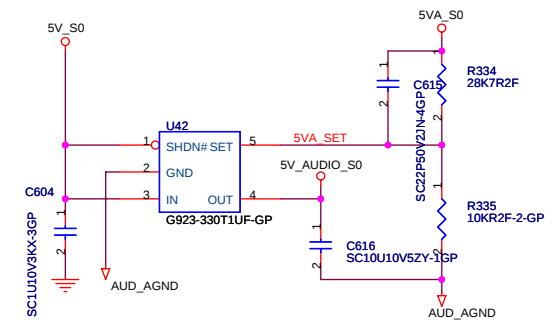
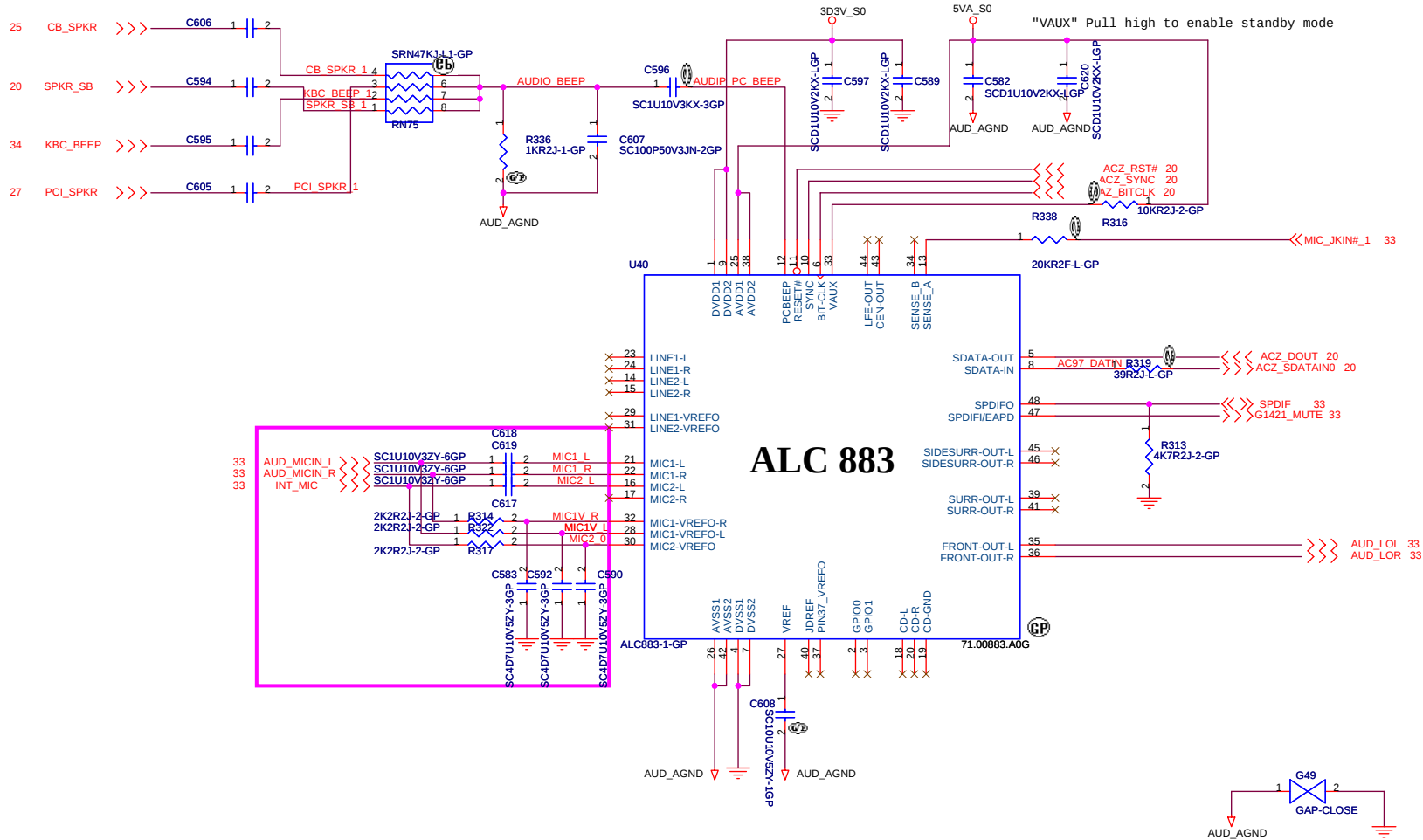


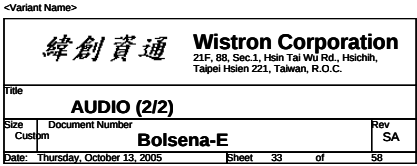
<Variant Name>

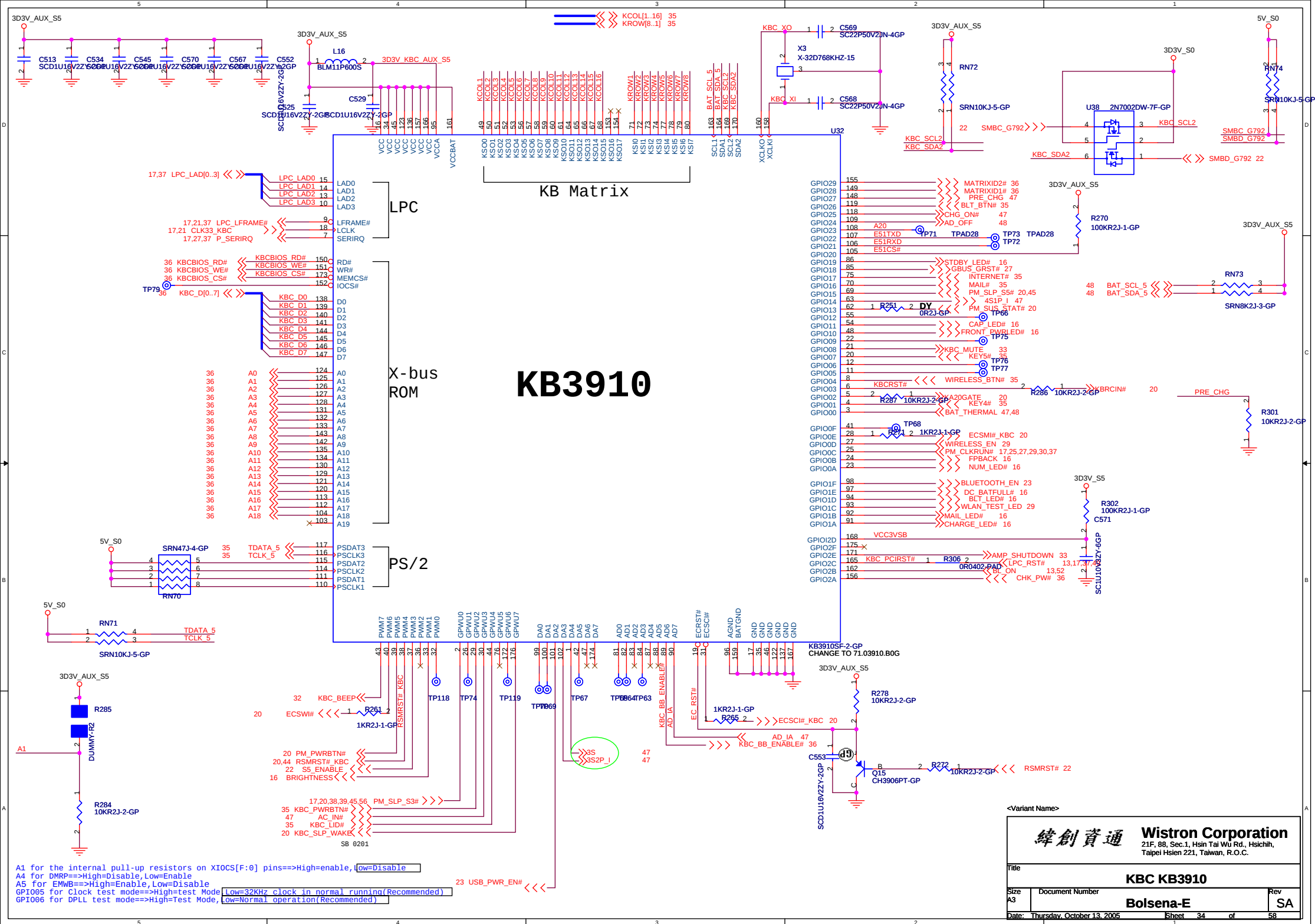
緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
MINI-PCI			
Size A3	Document Number		Rev SA
Bolsena-E			
Date:	Thursday, October 13, 2005	Sheet 29 of	58

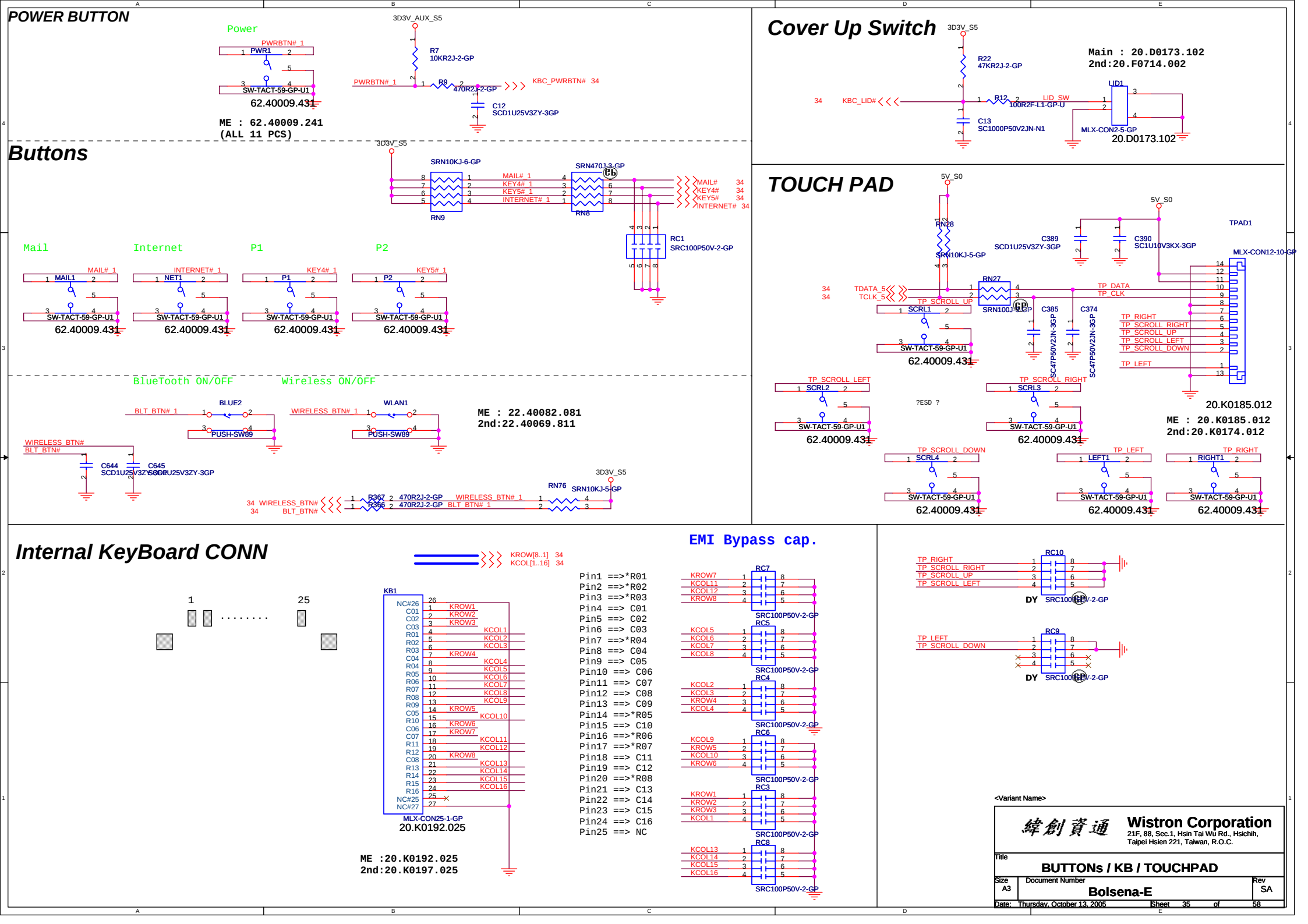


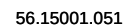




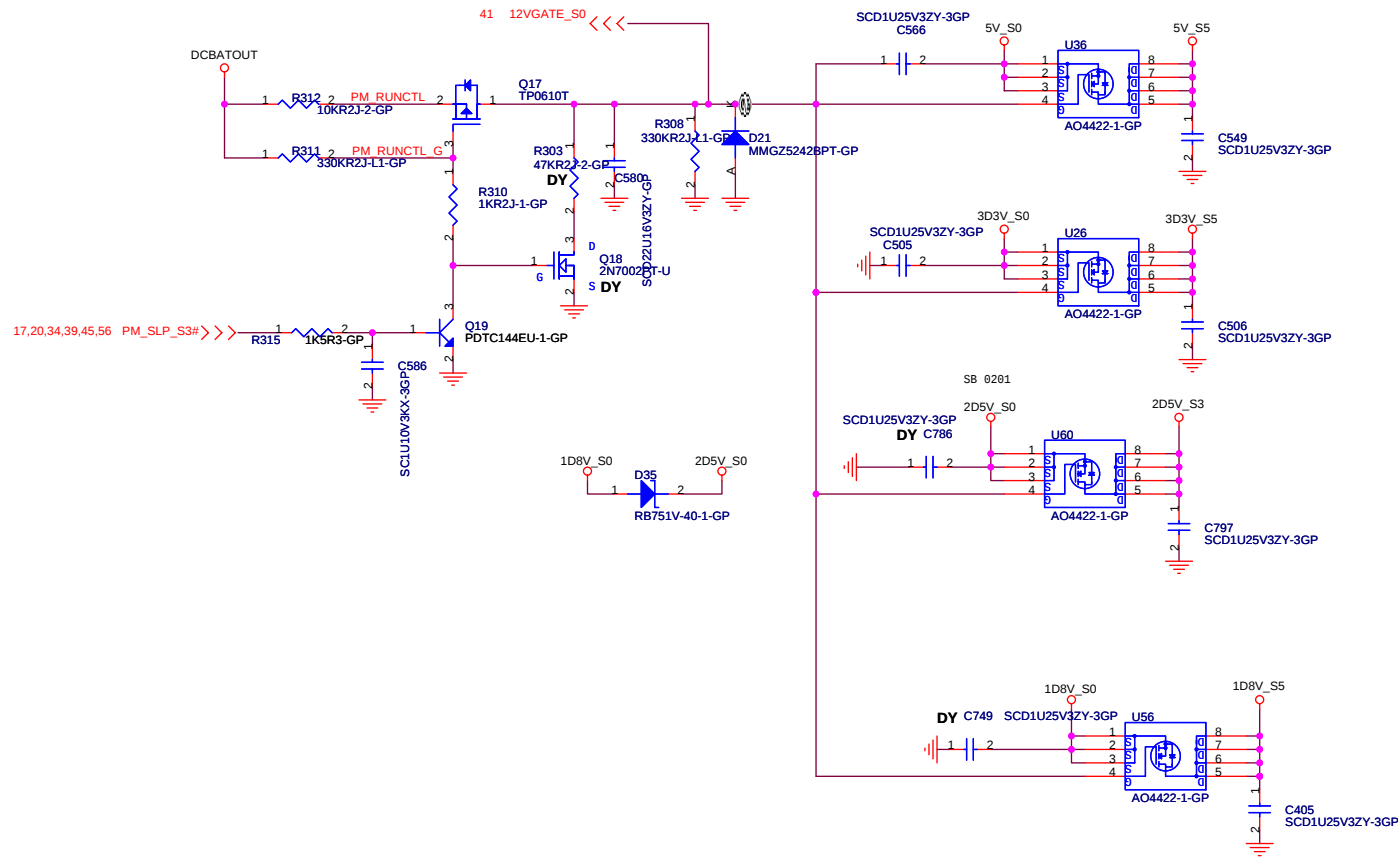


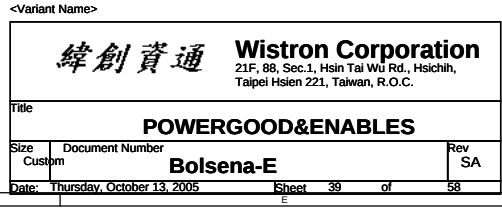




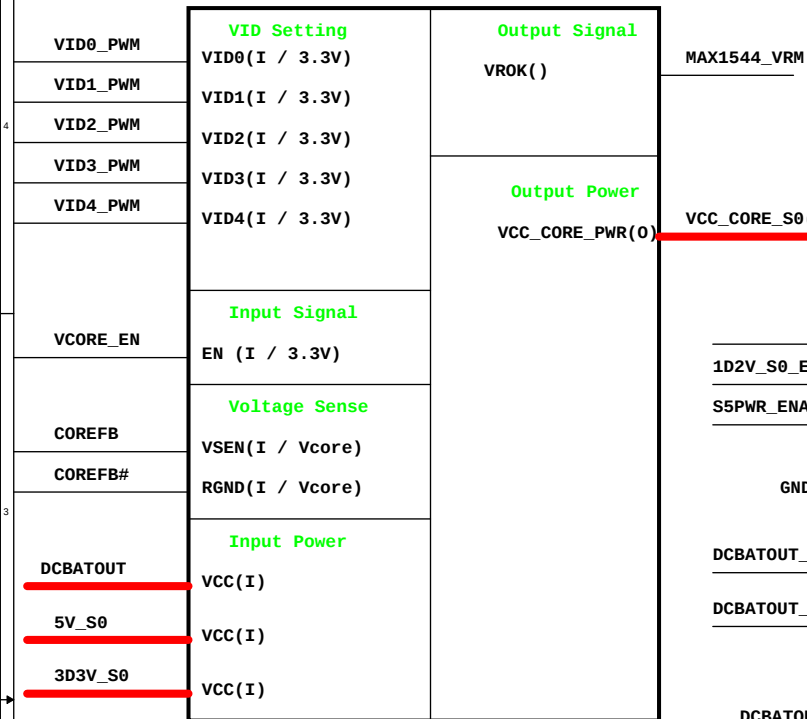


Run Power

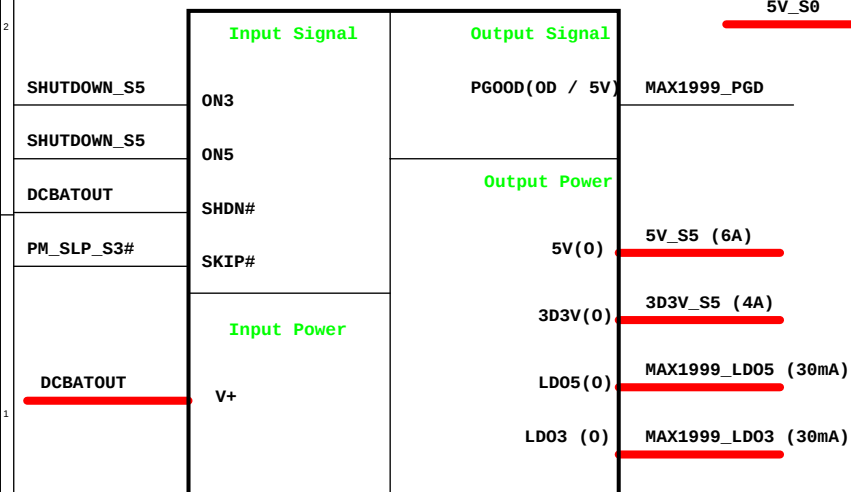




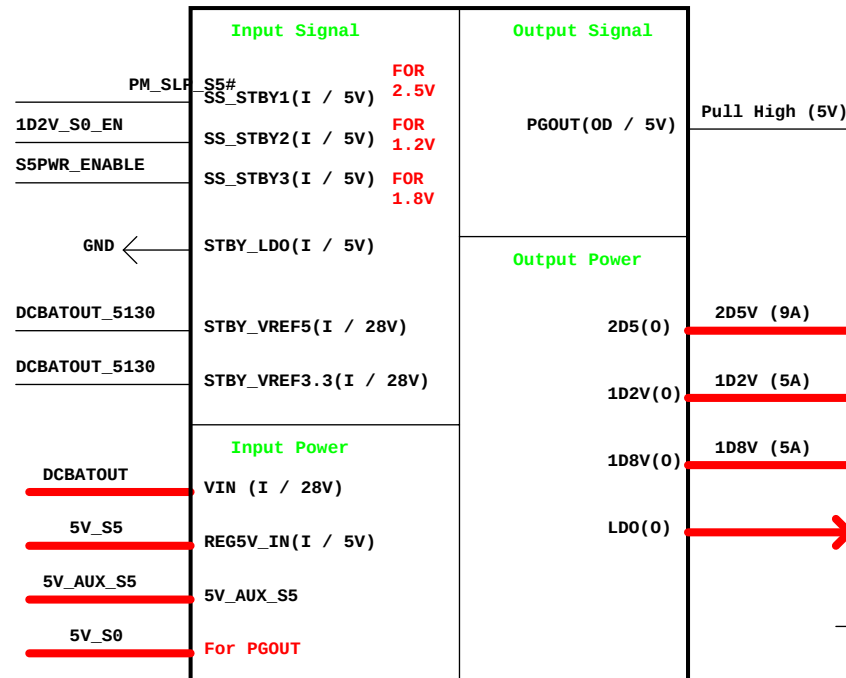
CPU_CORE MAX1544ETL



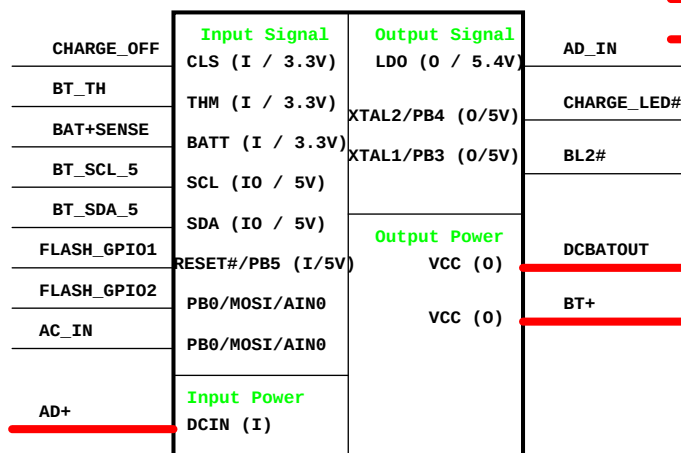
TPS51120 5V/3D3V



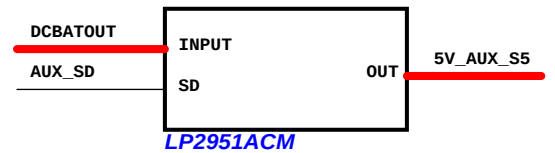
TI TPS5130 2D5V/1D2V/1D8V



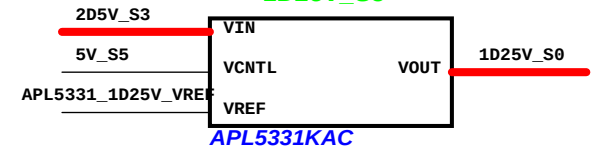
Charger_Max8725



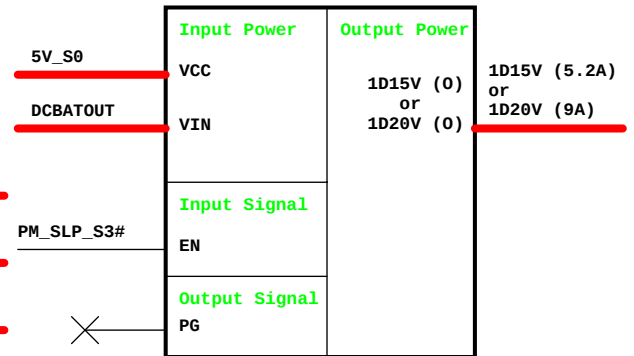
5V_AUX_S5



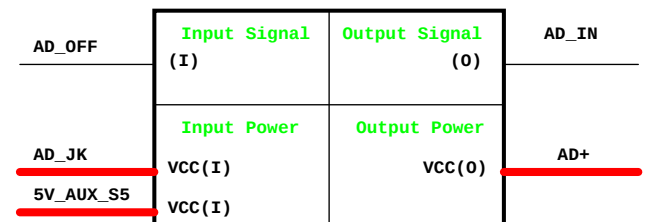
1D25V_S3



FAN5234_VGA_Core 1D15V or 1D20V



Adapter



<Variant Name>

緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title			
POWER BLOCK DIAGRAM			
Size A3	Document Number		Rev SA
Date: Thursday, October 13, 2005	Bolsena-E		Sheet 40 of 58

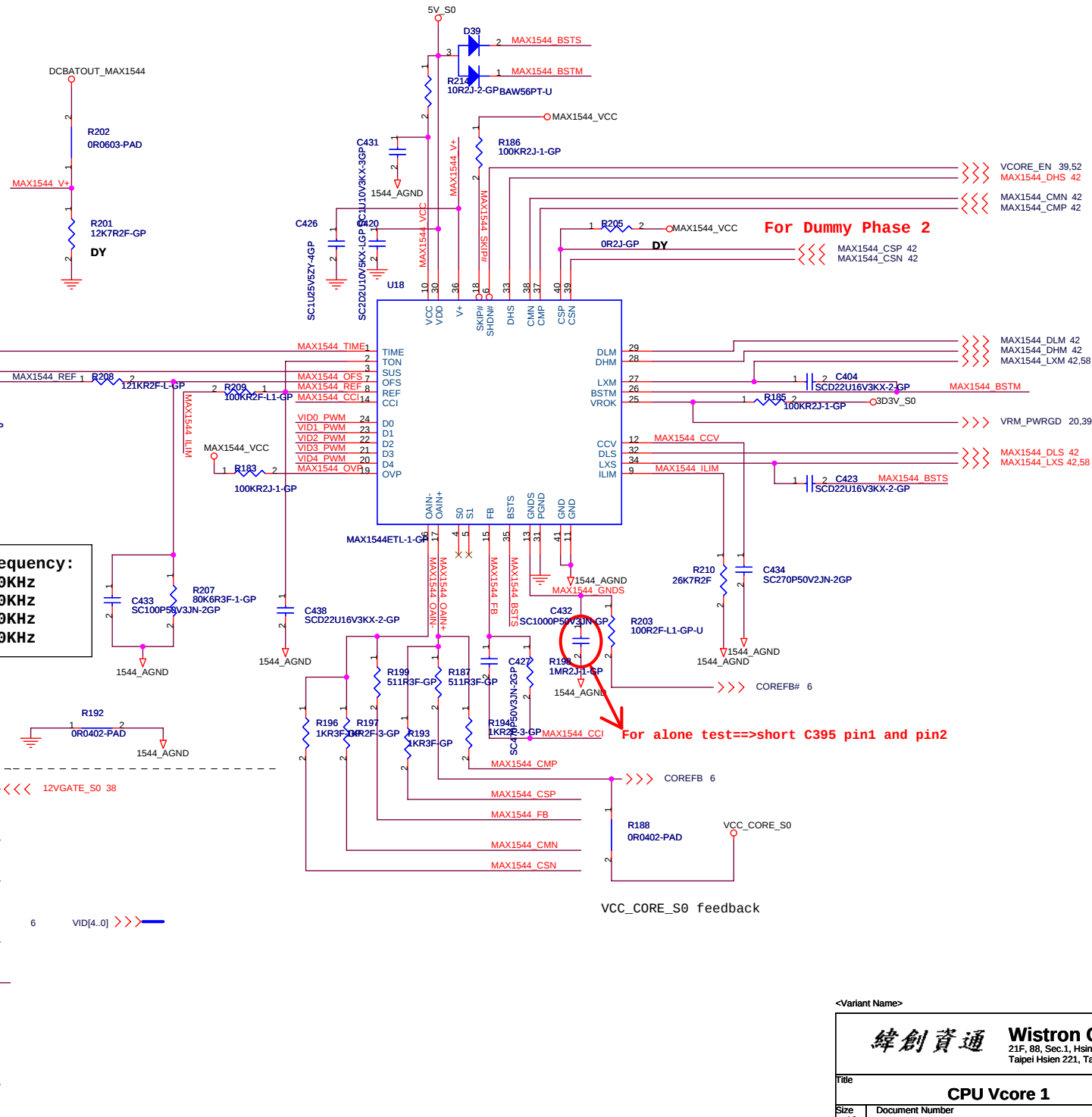
(Power Team)

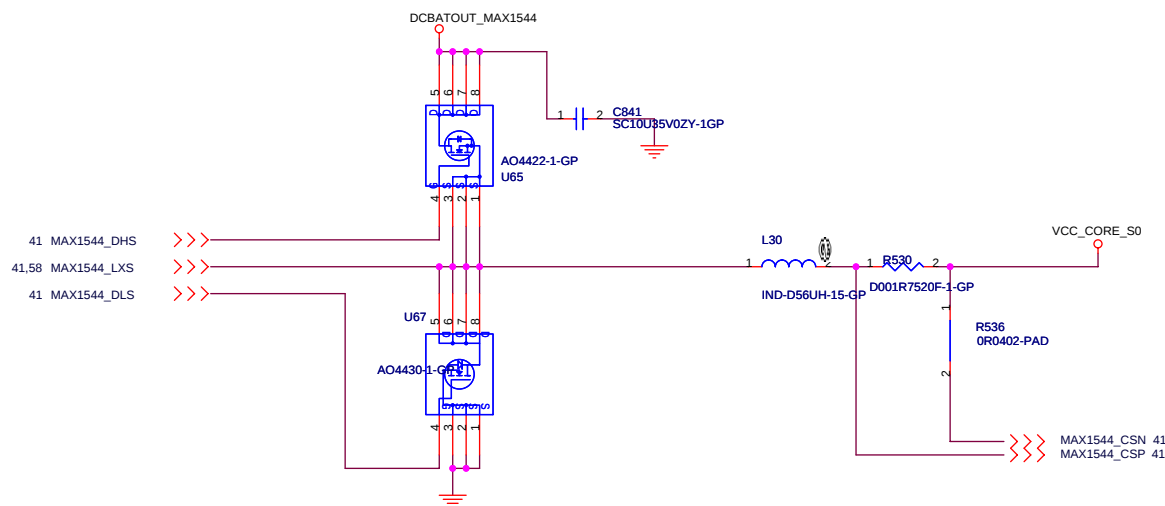
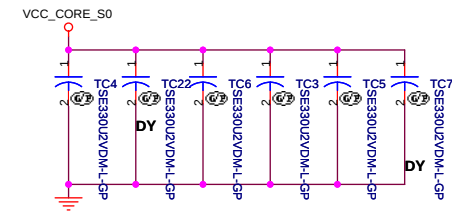
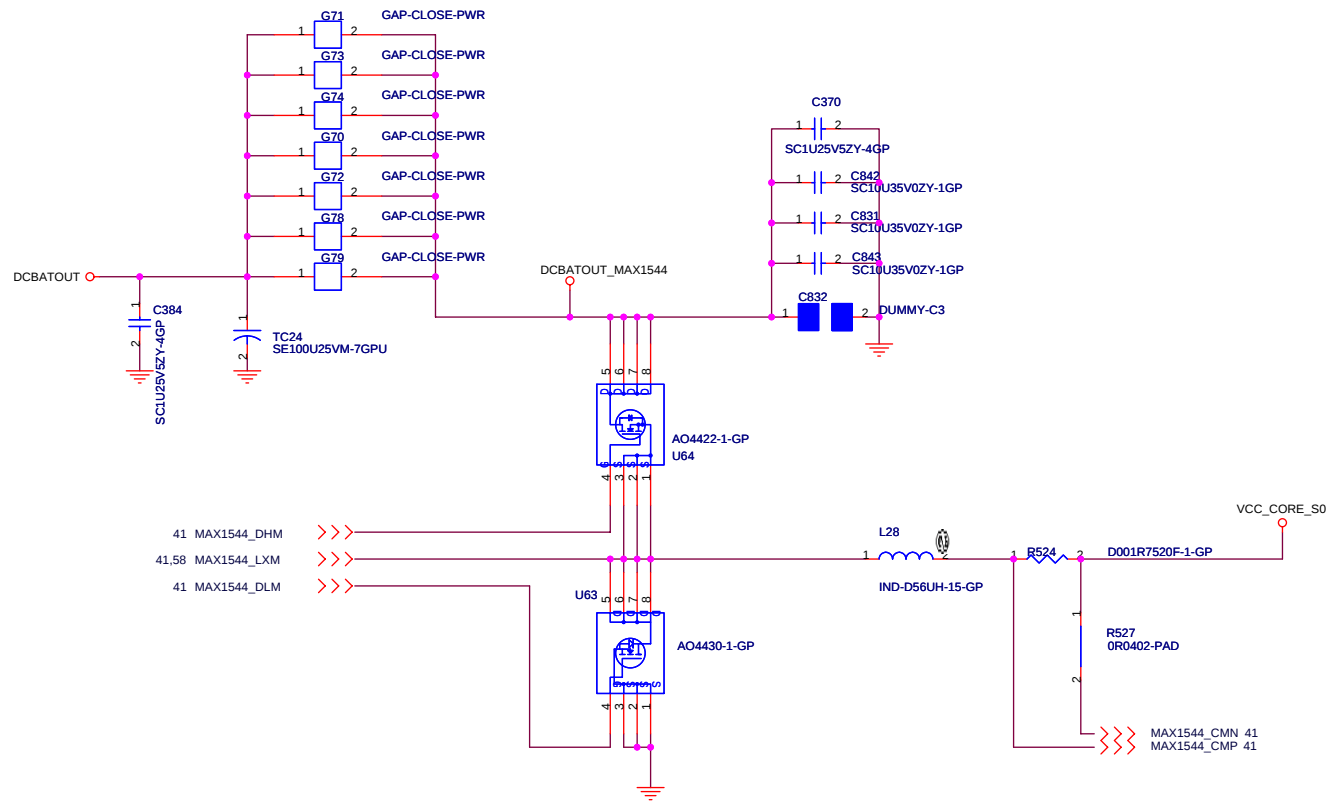
CPU_VCORE
VID=1.20V
Iomax=27.3A (35W)
OCP=40A~45A

TABLE 1. VOLTAGE IDENTIFICATION CODES					
VID4	VID3	VID2	VID1	VID0	DAC
0	0	0	0	0	1.550
0	0	0	0	1	1.525
0	0	0	1	0	1.500
0	0	0	1	1	1.475
0	0	1	0	0	1.450
0	0	1	0	1	1.425
0	0	1	1	0	1.400
0	0	1	1	1	1.375
0	1	0	0	0	1.350
0	1	0	0	1	1.325
0	1	0	1	0	1.300
0	1	0	1	1	1.275
0	1	1	0	0	1.250
0	1	1	0	1	1.225
0	1	1	1	0	1.200
0	1	1	1	1	1.175
1	0	0	0	0	1.150
1	0	0	0	1	1.125
1	0	0	1	0	1.100
1	0	0	1	1	1.075
1	0	1	0	0	1.050
1	0	1	0	1	1.025
1	0	1	1	0	1.000
1	0	1	1	1	0.975
1	1	0	0	0	0.950
1	1	0	0	1	0.925
1	1	0	1	0	0.900
1	1	0	1	1	0.875
1	1	1	0	0	0.850
1	1	1	0	1	0.825
1	1	1	1	0	0.800
1	1	1	1	1	Shutdown

TON: Frequency:
GND 550KHz
REF 300KHz
OPEN 200KHz
VCC 100KHz

From KBC





SB 0203

<Variant Name>

緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
CPU Vcore 2		
Size	Document Number	Rev
A3	Bolsena-E	SA
Date: Thursday, October 13, 2005		
Sheet 42 of 58		

(Power Team)



For TPS51120,
Vout=5V

1. If you use a 6.8uH inductor, the minimum ESR is 70m ohm.
2. If you use a 4.7uH inductor, the minimum ESR is 48m ohm.
3. If you use a 3.3uH inductor, the minimum ESR is 34m ohm.

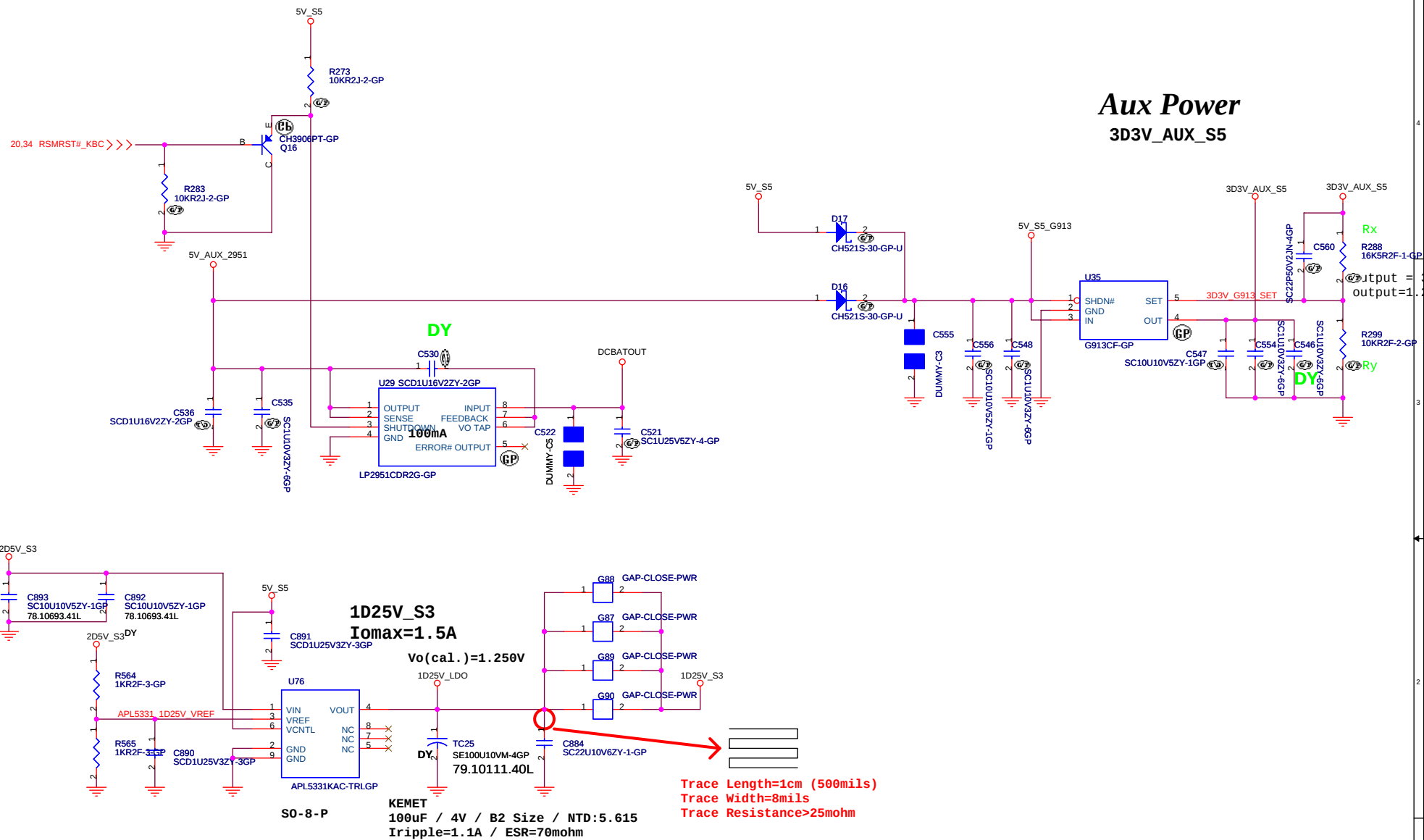
Vout=3.3V

1. If you use a 4.7uH inductor, the minimum ESR is 51m ohm.
2. If you use a 3.3uH inductor, the minimum ESR is 36m ohm.
3. If you use a 2.5uH inductor, the minimum ESR is 27m ohm.

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Rev

Sheet 43 of 58



<Variant Name>

緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title 1D2V_S3 / 3D3V_AUX			
Size A3	Document Number Bolsena-E		Rev SA
Date: Thursday, October 13, 2005		Sheet 44	of 58

(Power Team)

(1D2V=>CH1 , 1D8V=>CH2 , 2D5V =>CH3)

close to IC

close to IC

close to IC

TPS5130

close to IC

0_OUT2U >>> 513

-1 0310

5130 5V LDO 51

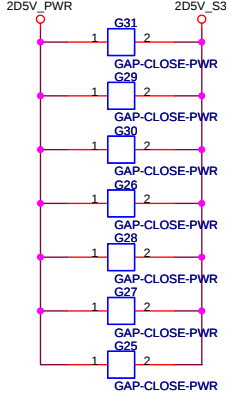
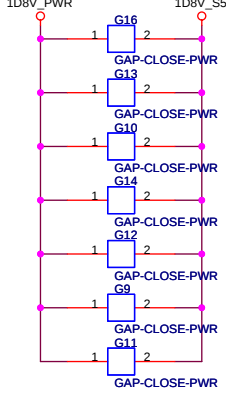
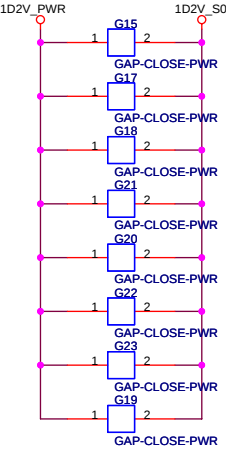
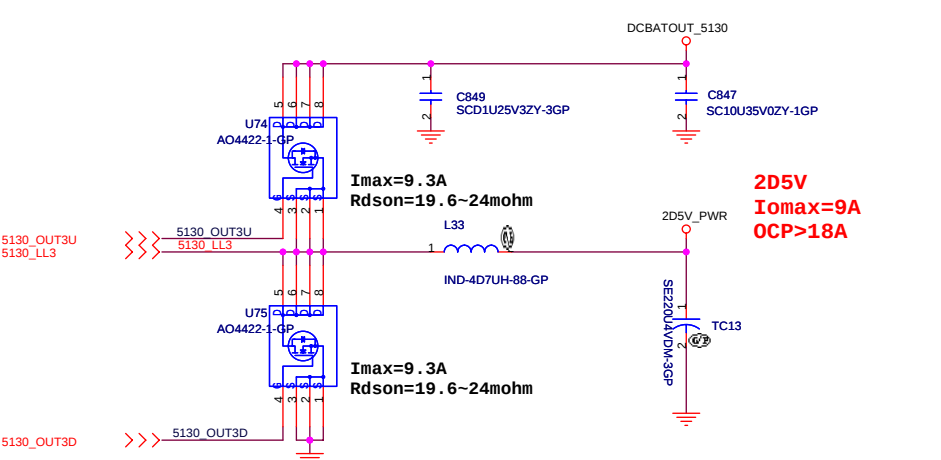
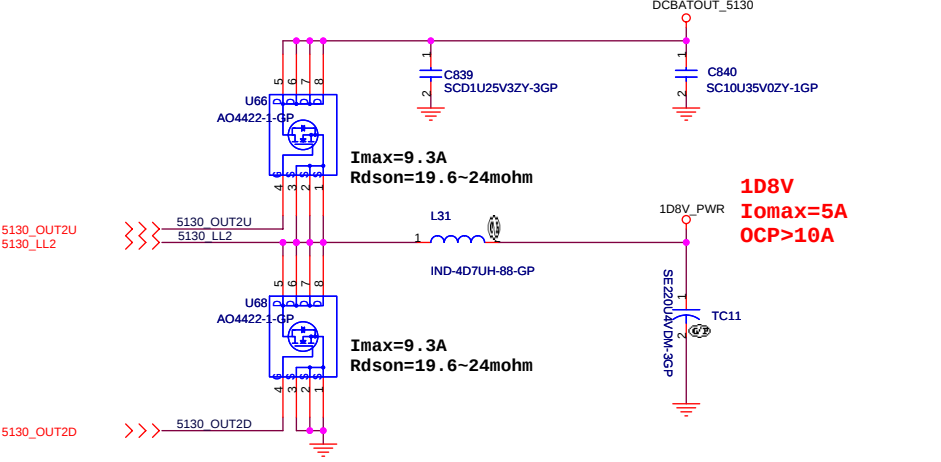
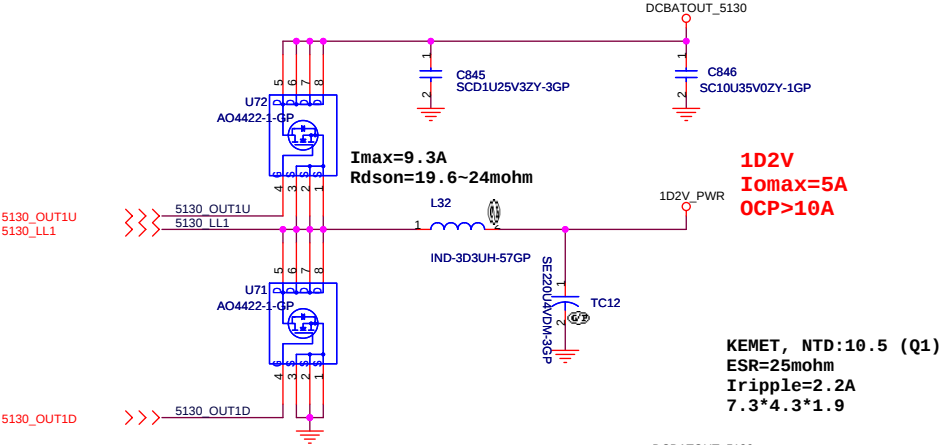
2

 78.47593.41L

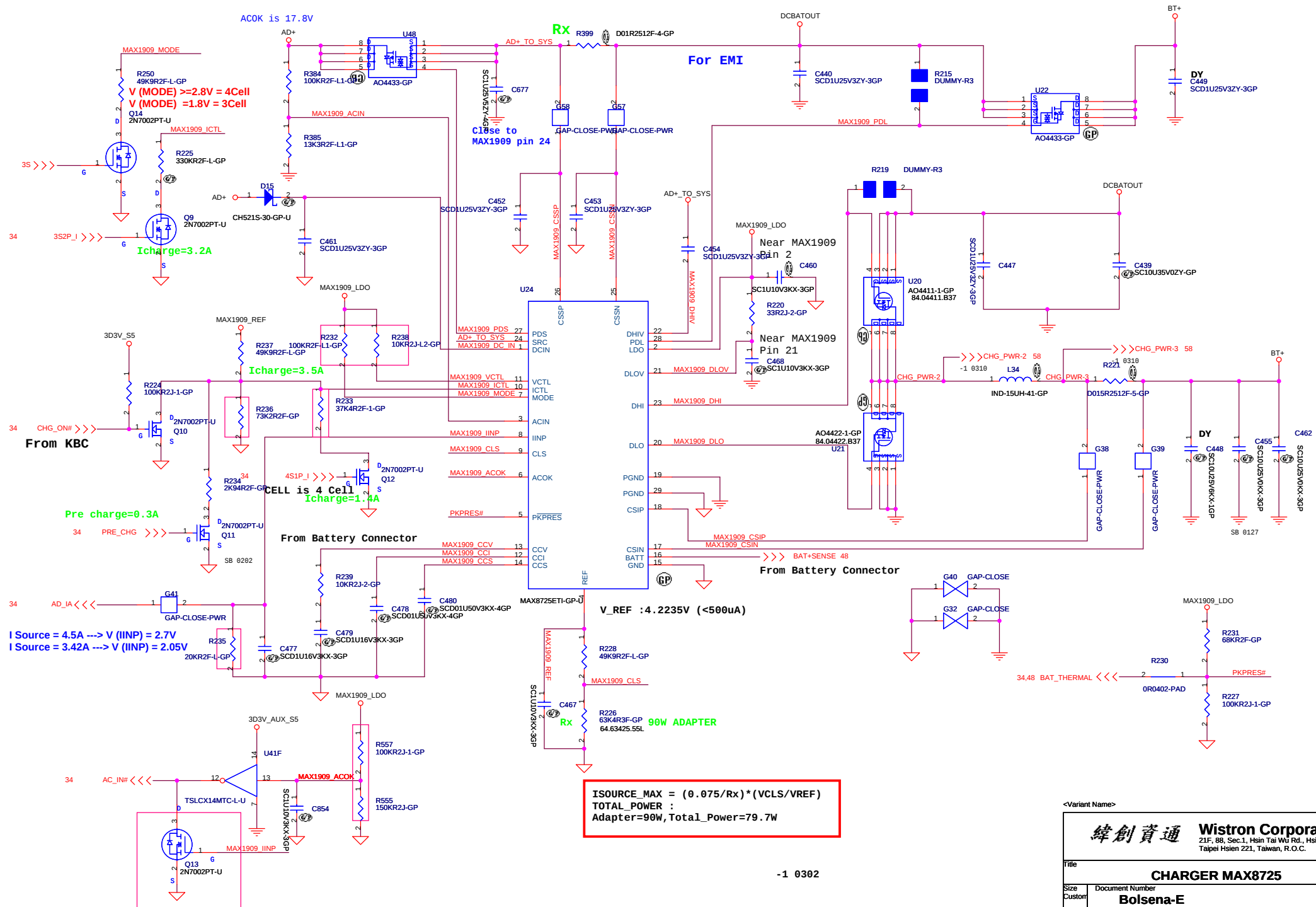
Size A3	Document Number Bolsena-E	Rev SA
Date: Thursday, October 12, 2006	Sheet 45 of 58	

(Power Team)

TI TPS5130 for 2D5V, 1D2V, 1D8V
(1D2V=>CH1 , 1D8V=>CH2 , 2D5V =>CH3)



```
AC_IN Threshold 2.089V Max.  
AC_IN > 2.089V --> AC DETECT
```



[illegible]

BATTERY CONNECTOR

5V_AUX_S5

BAV99PT-GP-U D42

BAV99PT-GP-U D41

R552 27R3F-GP

R553 27R3F-GP

R554 0R0402-PAD

R555 27R3F-GP

BT+ 34 BAT_SCL_5 34,47 BAT_SDA_5 47 BAT_THERMAL_5 47 BAT+SENSE_5

SCD1U50V3ZV-GP C851

SCD1U50V3ZV-GP C852

SCL1K50V2ZV-GP C853

SCL1K50V2ZV-GP C854

SCL1K50V2ZV-GP C855

EC68

EC66

BAT1

AMP-CON7-S-GP

20.80604.007

ME :20.80604.007

2nd:20.80269.007

Put close to battery connector

it :

L3# at 11.25V

DCBATOUT

R213
1MR2J-1-GP
DY

HTH

DY
R212
15KR2F-GP

HTH

DY
R211
110KR2F-GP

U19
G680LT1F-GP
Output type: DY
Open-Drain RESET#

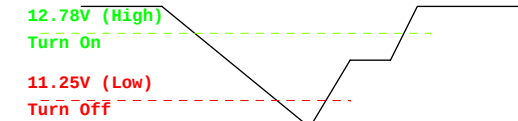
HTH
GND
LTH

VCC
RESET#/RESET

DY
C435
SCD1U10V2KX-LGP

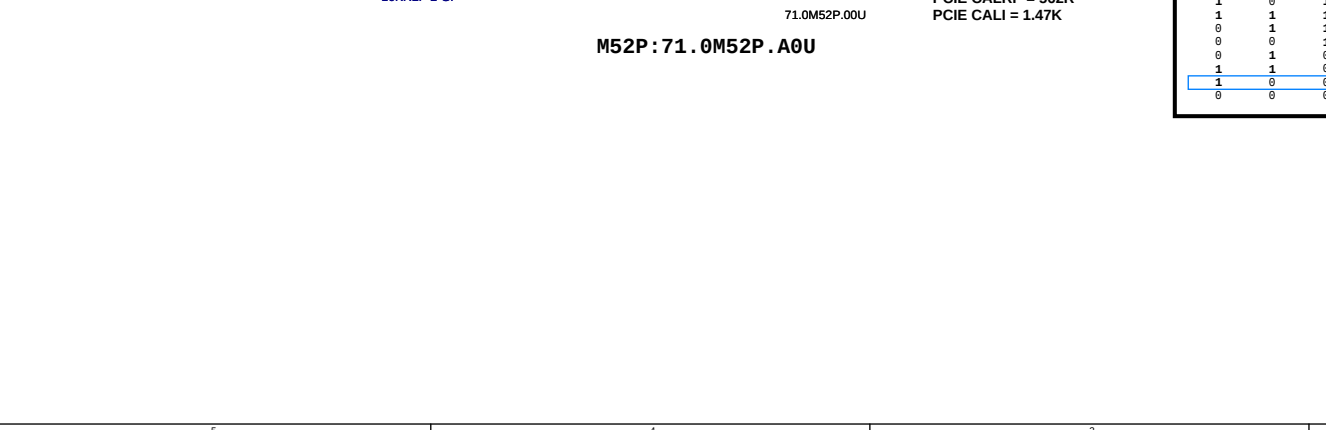
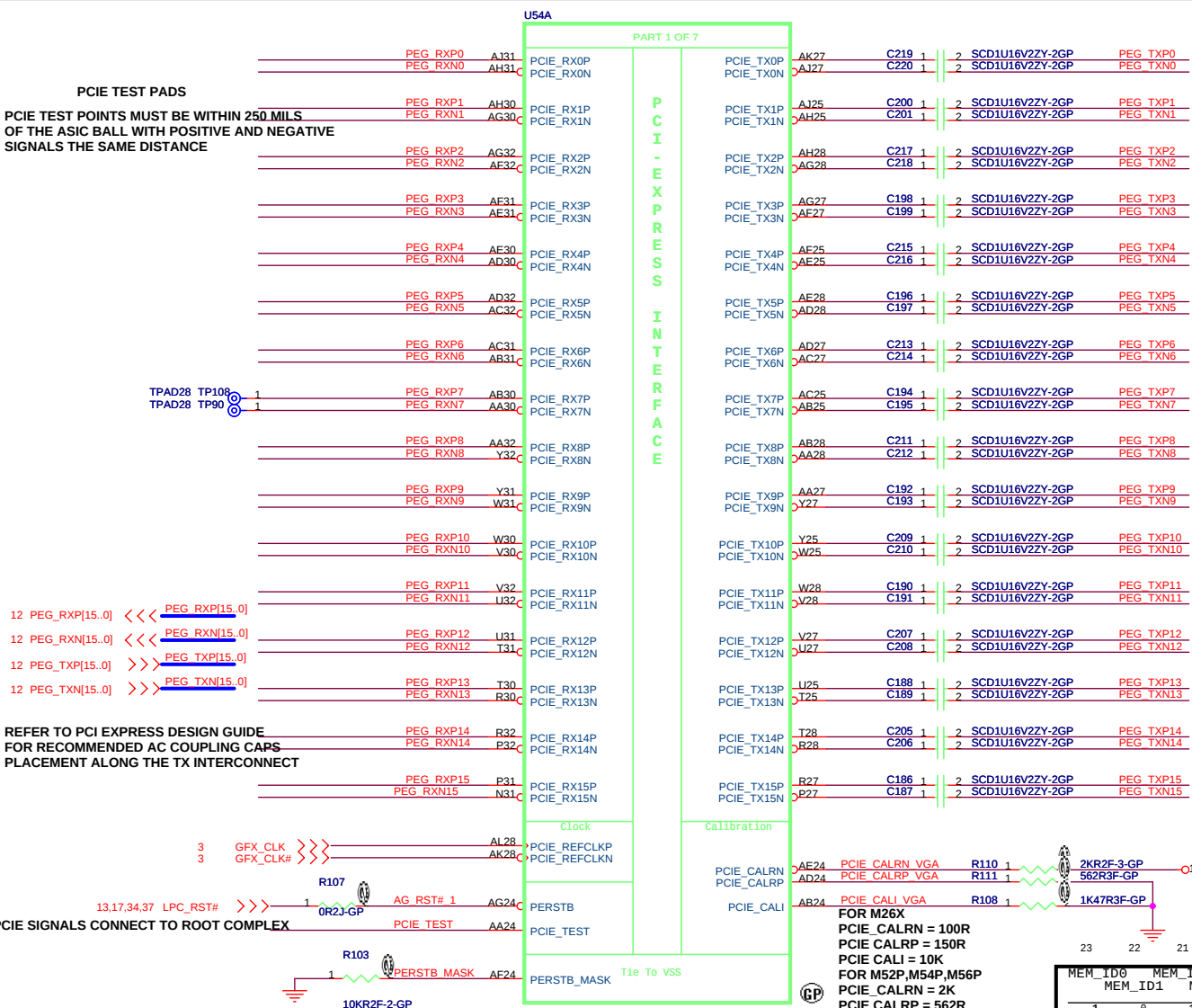
MAX1999_LDO5

>>>LOW3_OFF 22

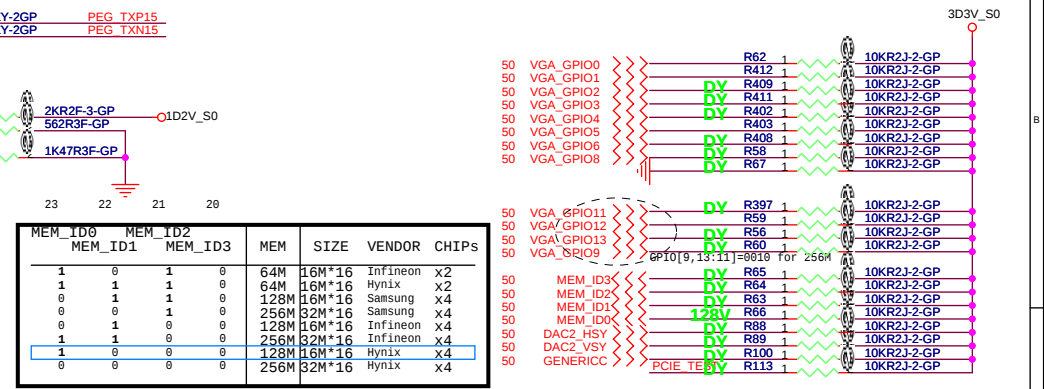


緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
AD/BATT CONN			
Size	Document Number	Rev	
A3	Bolsena-E	SA	
Date: Thursday, October 13, 2005		Sheet 48	of 58



STRAPS	PIN	DESCRIPTION OF RECOMMENDED SETTING	RECOMMENDED
STRAP_B_PTX_PWRS_ENB	GPIO0	TRANSMITTER POWER SAVINGS ENABLE - FULL TX OUTPUT SWING	INSTALL 10K RESISTOR
STRAP_B_PTX_DEEMPH_EN	GPIO1	TRANSMITTER DE-EMPHASIS ENABLE DEPENDS ON PCIE CHIPSET BEING USED FOR M26X,M5X INSTALL WITH ATI RS480,RS400,RX480, RC410,RS482 CHIPSETS FOR M26X ONLY DO NOT INSTALL WITH INTEL 915PM CHIPSET	TBD
RSVD	GPIO(3:2)	NO ATI FEATURE ENABLED	DO NOT INSTALL 10K RESISTORS
REVERSE LANES DEBUG ACCESS	GPIO4	NOT REVERSED LANE (M26X) NO DEBUG ACCESS (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTOR
STRAP_FORCE_COMPLIANCE sets the desired PCIE PLL bandwidth for M5x parts.	GPIO5	DO NOT FORCE COMPLIANCE STATE QUICKLY (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	INSTALL 10K RESISTORS
COMMON MODE RANGE RSVD	GPIO6	NORMAL RANGE (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
DEBUG ACCESS FORCE_COMPLIANCE	GPIO8	NO DEBUG ACCESS (M26X) DON'T FORCE COMPLIANCE STATE(M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
ROMIDCFG(3:0)	GPIO[9:13:11]	SERIAL FLASH ROM TYPE (M26X,M52P,M54P,M56P) - SERIAL M25P10 ROM	1011
MEMORY APERTURE SIZE	GPIO[13:11]	IF NO ROM GPIO11(M26X) AND GPIO12,13(M52,M54,M56) SET MEMORY APERTURE SIZE SEE M26X,M54X,M56X DATA BOOK FOR MEMORY,FRAME BUFFER APERTURE SETTINGS	TBD
MEM_TYPE	MEMID (3:0)	MEMORY TYPE AND SPEED SELECT	TBD
RSVD NO STRAP FUNCTION	H2SYNC V2SYNC GENERICC	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	DO NOT INSTALL 10K RESISTORS
RSVD NO STRAP FUNCTION	PCIE_TEST	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	



MEM_ID0	MEM_ID1	MEM_ID2	MEM_ID3	MEM	SIZE	VENDOR	CHIPS
1	0	1	0	64M	16M*16	Infineon	x2
1	1	1	0	64M	16M*16	Hynix	x2
0	1	1	1	128M	16M*16	Samsung	x4
0	0	1	0	256M	32M*16	Samsung	x4
0	1	0	0	128M	16M*16	Infineon	x4
0	1	0	0	256M	32M*16	Infineon	x4
1	0	0	0	128M	16M*16	Hynix	x4
0	0	0	0	256M	32M*16	Hynix	x4

When no ROM is attached, GPIO[9] is set to 0.
GPIO[13:12] is used to select the frame buffer aperture size.
GPIO[13:12] = 00: 128M frame buffer, same as ROM strap 00
GPIO[13:12] = 01: 256M frame buffer, same as ROM strap 01
GPIO[13:12] = 10: 64M frame buffer, same as ROM strap 10
GPIO[13:12] = 11: reserved, same as ROM strap 11

<Variant Name>

Title		
Size A3		
Date: Thursday, October 13, 2005		
Sheet 49 of 58		
Rev SA		

ATI M5X-P PCIE 1/4

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.



1D8V_S0

R71

100R2F-L1-GP-U

R72

100R2F-L1-GP-U

1D8V_S1

R49

100R2F-L1-GP-U

R55

100R2F-L1-GP-U

C90

SCD85V2KX-1GP

C75

SCD85V2KX-1GP

MVREFD1

MVREFS1

MEM_RST

TEST_MCLK

TEST_YCLK

MEMTEST

RN10

SRN4K7J-6-GP

Pin	Label
QDB_58	MDB58 R7
QDB_59	MDB59 T7
QDB_60	MDB60 V7
QDB_61	MDB61 W7
QDB_62	MDB62 W8
QDB_63	MDB63 W9

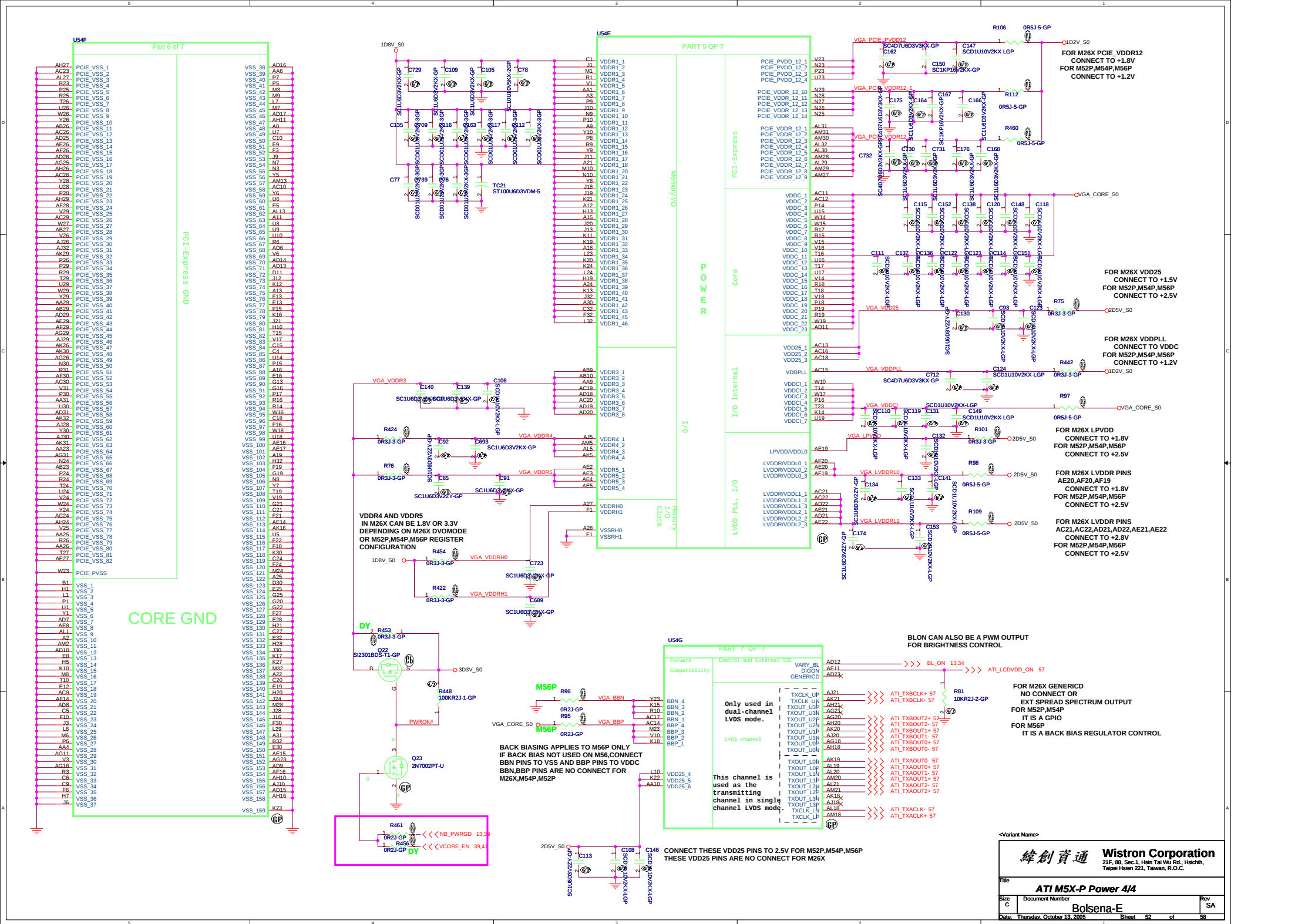
**PLACE MVREF DIVIDERS
AND CAPS CLOSE TO ASIC**

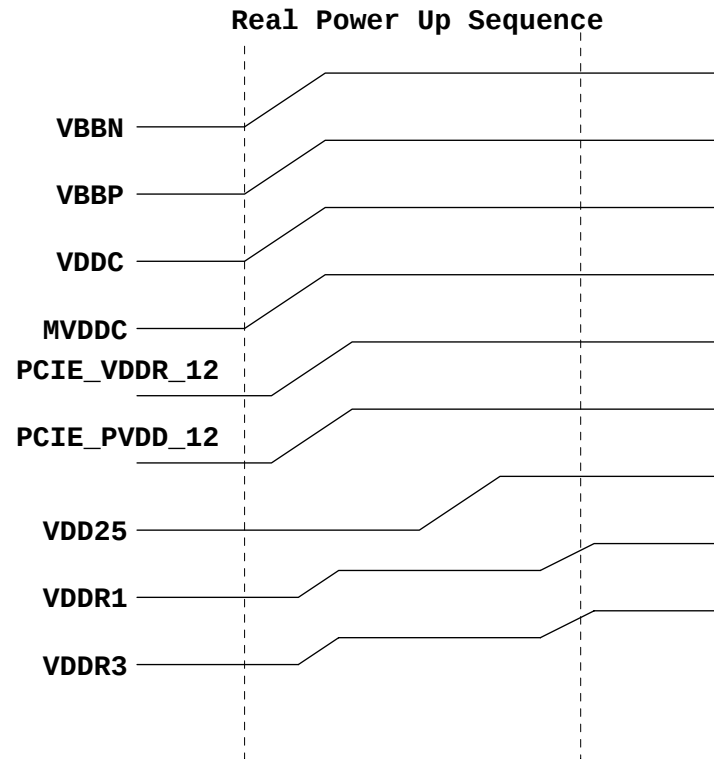
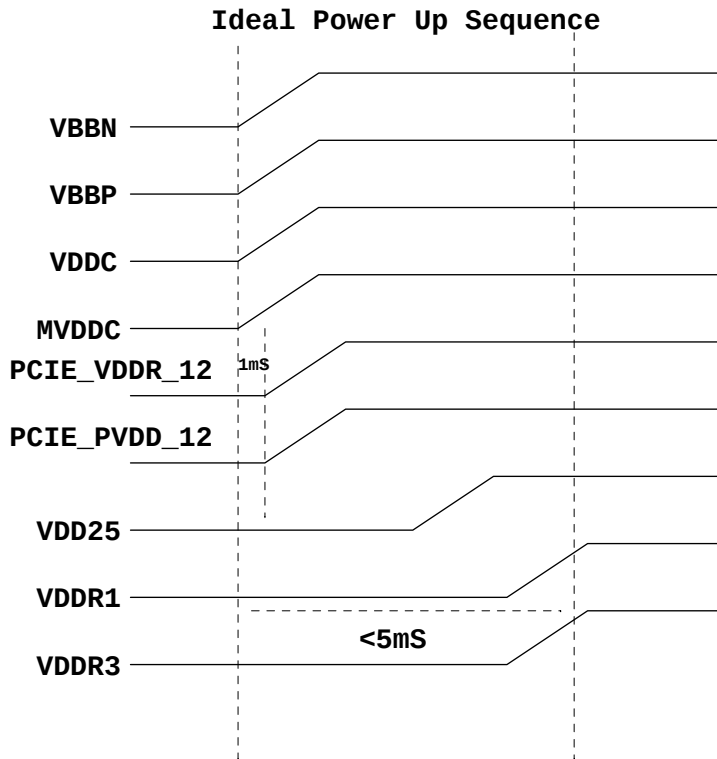


<Variant Name>

緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
ATI M5X-P MEM 3/4			
Size A3	Document Number		Rev
	Bolsena-E		SA
Date:	Thursday, October 13, 2005	Sheet 51 of	58





RESISTOR

Symbol name	Value	Tolerance (J: 5%, F: 1%, D: 0.5%, B: 0.1 %)	Rating 0402=> 1/16W, 25V 0603 => 1/16W, 75V 0805 => 1/10W, 100V	Size 2=>0402, 3=>0603, 5=>0805 6=>1206, 0=>1210
10KR3	10K Ohm	If no letter, it means J: 5%	1/16W, 75V	0603
33D3R5	33.3 Ohm	If no letter, it means J: 5%	1/10W, 100V	0805
1KR3F	1K Ohm	F: 1%	1/16W, 75V	0603

The naming rule is value + R + size + tolerance
For the value, it can be read by the number before R. (R means resistor)
For the tolerance, it can be read from the last letter.
For the rating, we don't show on the symbol name.
For the size, R2=>0402, R3=>0603, R5=>0805,.....

General Guidelines:

- BBN and BBP must ramp up before or at the same time as VDDC but not after.
- VDDC and MVDDC must be ramped up first, followed by PCIE_VDDR_12, PCIE_PVDD12, VDD25, VDDR1 and VDDR3 (and other I/O powers).
- All powers must be ramped up within 5ms of each other (from the ramp of VDDC to 90% of VDDR3).
- VDD25 can be ramped with VDDC or VDDR1 but it cannot be ramped later than VDDR1.
- The power down is the opposite of the power on sequence: VDDR3/VDDR1 -> VDD25 ->VDDC/MVDDC/BBN/BBP

Due to the level shifter design in the memory I/Os, in order to avoid over-stressing the thin oxide transistors when VDDR1 is powered on but VDDC is not, VDDC must ramp up before VDDR1. Similarly, VDDC must ramp up before VDDR3. The level shifter design is a function of the transistor types used in 90nm technology and of the voltage level support. The drawback of ramping up VDDC before the I/O voltages (such as VDDR1 and VDDR3) is that parasitic P/N junctions are forward biased, thus creating a conduction path. These conduction paths will pump up VDDR1 (from the memory I/Os) and VDDR3 (from the GPIOs).

The real power up sequence will appear as follows:

Figure 2-2. Real Power Up Sequence

As long as MVDDC ramps up with VDDC, the pump voltage on VDDR1 should be all right since the DRAM spec will not be violated.

CAPACITOR

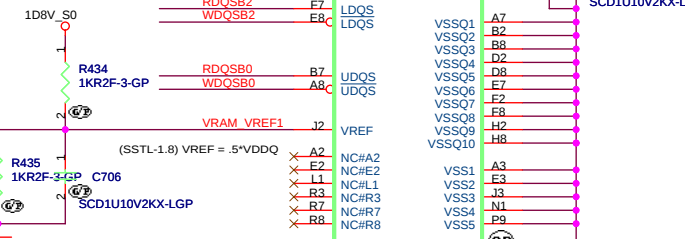
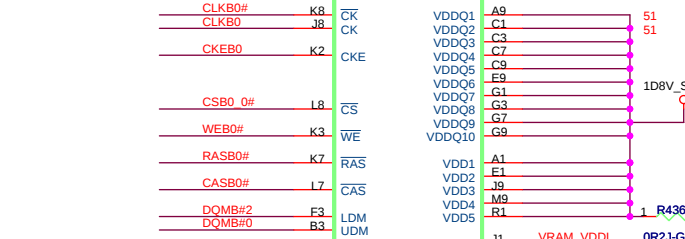
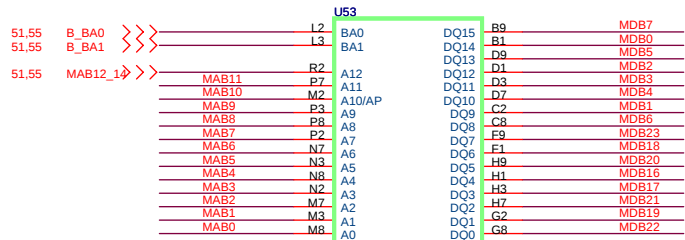
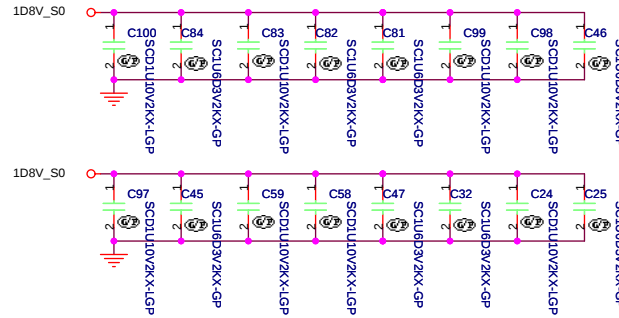
Symbol name	Value	Tolerance (J: +/-5, K: +/-10, M: +/-20, Z: +80/-20)	Rating (X5R / X7R < 80%, Y5V/Y5U/Z5U < 1/3)	Size 2=>0402, 3=>0603, 5=>0805 6=>1206, 0=>1210
SCD1U10V2MX-1	0.1uF	M/X5R	10V	0402
SC10U6D3V5MX	10uF	M/X5R	6.3V	0805
SC2D2U16V5ZY	2.2uF	Z/Y5V	16V	0805

The naming rule is
Capacitor type + value + rating + size + tolerance + material
SCD1U10V2MX-1
SC=> SMT Ceramic, TC=> POS cap or SP cap
D1U => 0.1uF
10V => the voltage rating is 10V
2=> 0402, 3=>0603, 5=>0805
M=>tolerance J, K, M, Z
X=> X7R/X5R, Y=> Y5V
-1 => symbol version, nonsense to EE characteristic

<Variant Name>

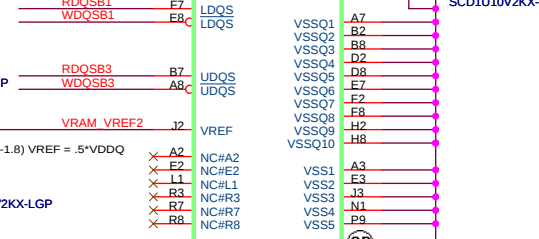
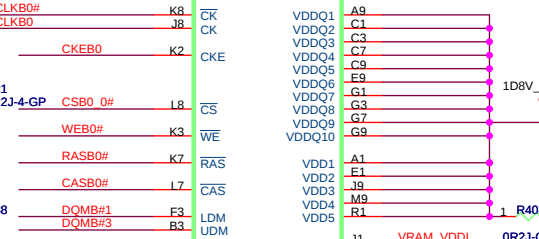
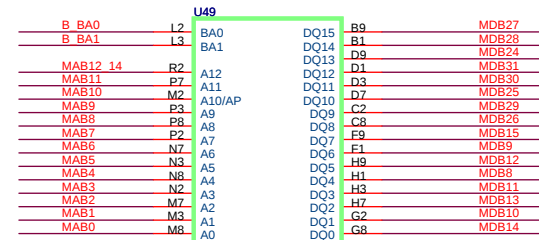
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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
ATI M5X-P POWER SEQUENCE			
Size	Document Number	Rev	SA
A3			
Date: Thursday, October 13, 2005		Sheet 53	of 58

CHAN B DDR2 84BGA 32MX16 MEMORY

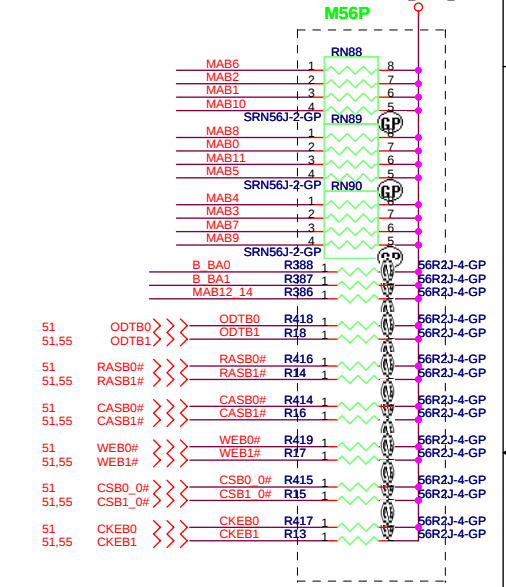


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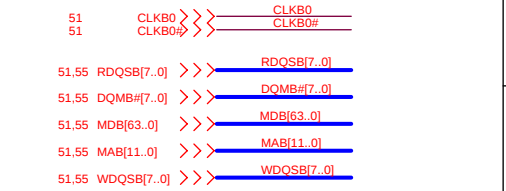
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72.51216.D0U IC VRAM HY5PS121621BFP-25 FBGA(32M*16, 400Mhz)



HY5PS561621A-25GP
72.55616.C0U



FOR M56P AT DDR2 MEMORY SPEEDS ABOVE 350MHZ
MEMORY CONTROL SIGNALS WE,CAS,RAS,CS,CKE,ODT
AND MEMORY ADDRESS SIGNALS REQUIRE 55 OHM PULLUP
TO A VTT RAIL (50% OF VDDQ)



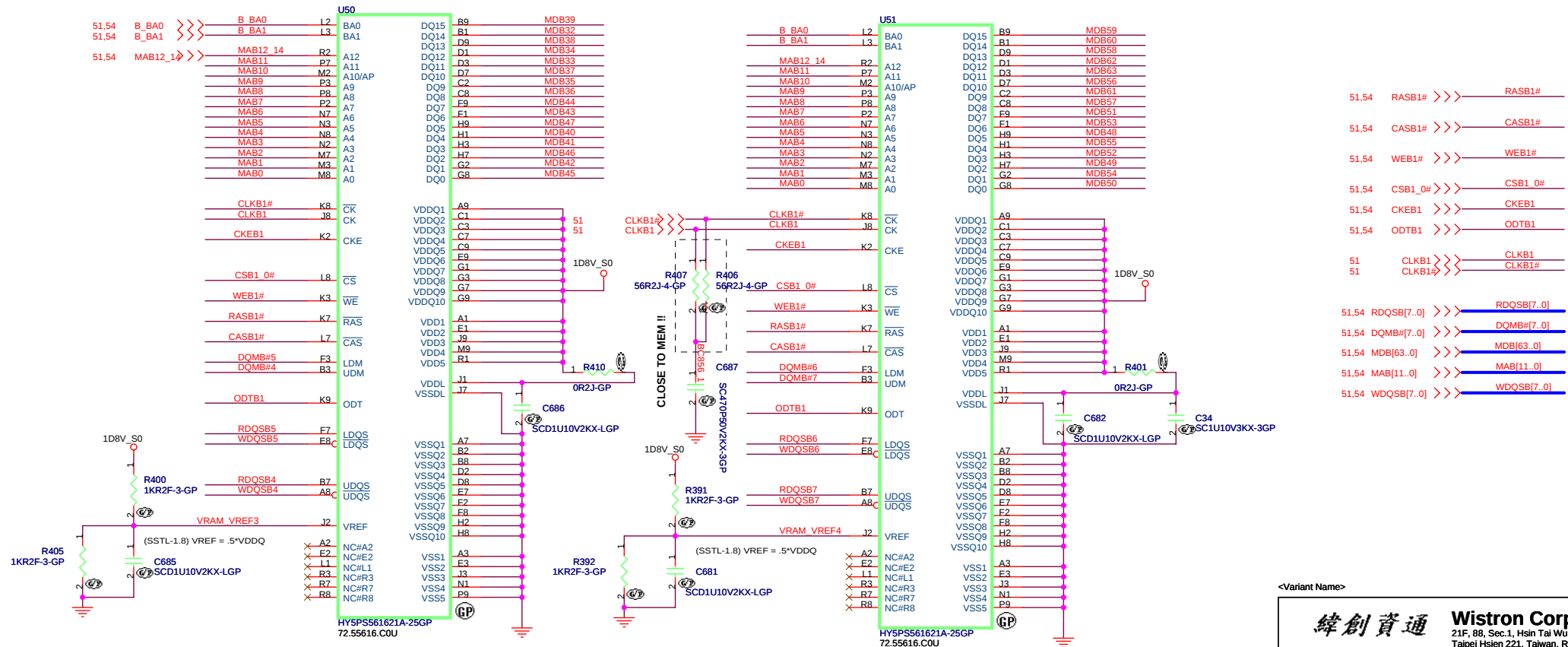
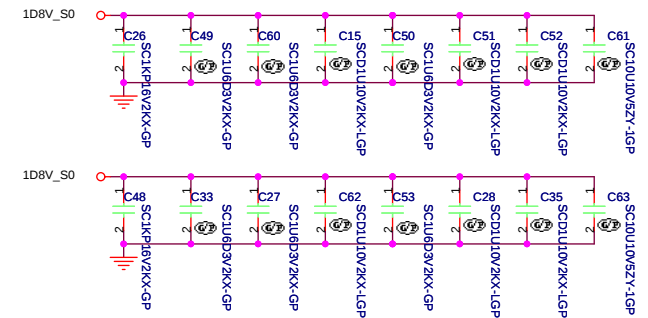
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Title: **VRAM 1/2**

Size: A3 Document Number: **Bolsena-E** Rev: SA

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<Variant Name>

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Title

VRAM 2/2

Size	A3
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Document Number

Bolsena-E

Rev
SA

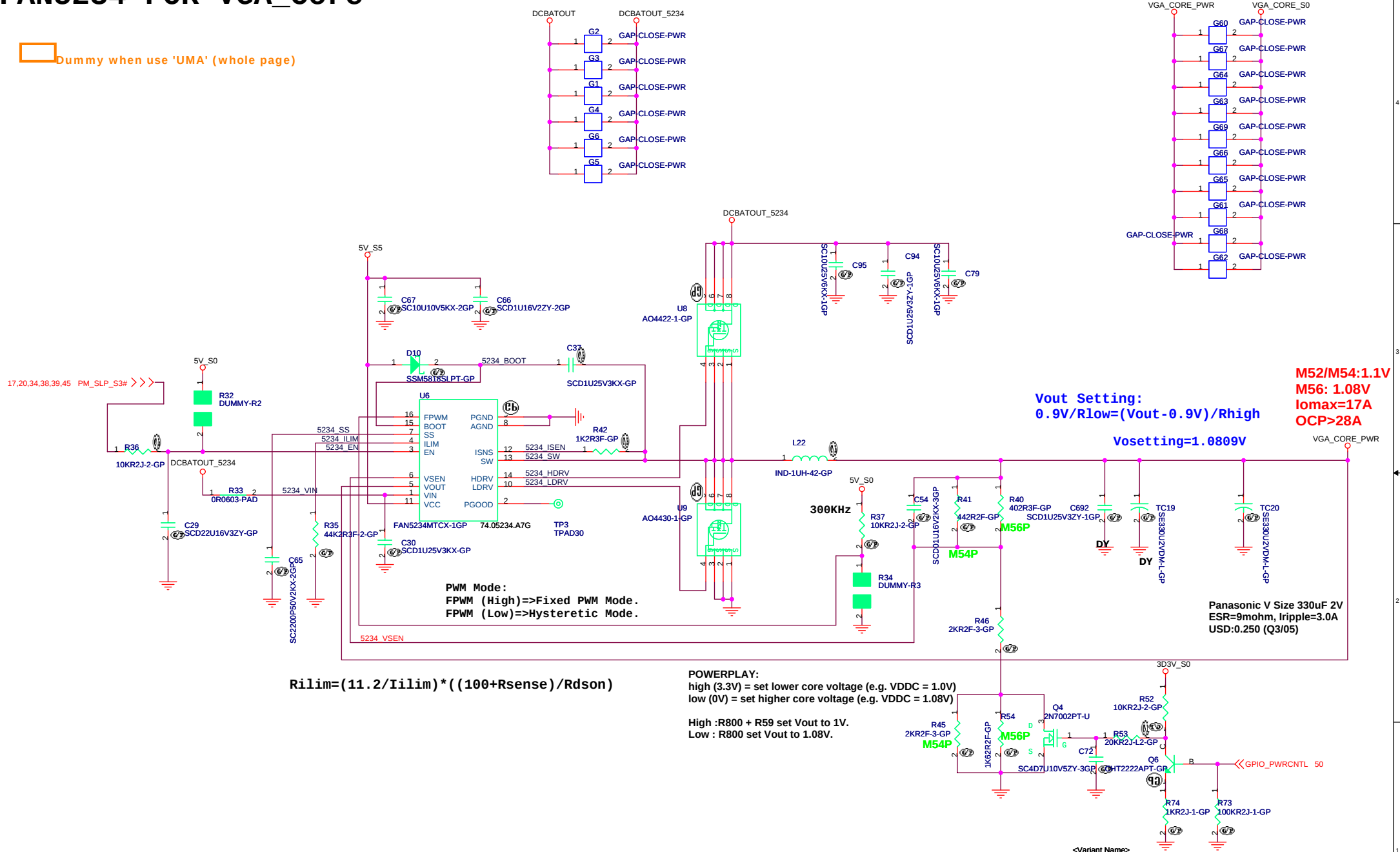
Date: Thursday, October 13, 2005

Sheet

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FAN5234 FOR VGA_Core

☐ Dummy when use 'UMA' (whole page)



<Variant Name>

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Title			
VGA CORE 1D1V			
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A3	Bolsena-E	SA	
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(Power Team)

TV SWITCH

Function	S
A to B0	L
A to B1	H

